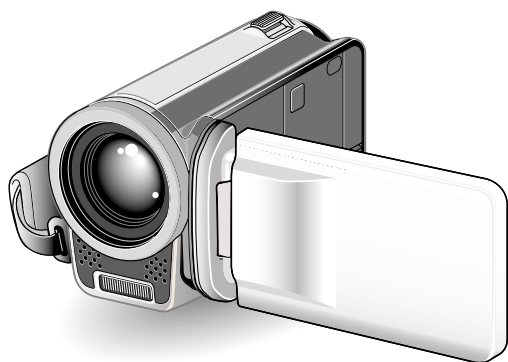




SERVICE MANUAL

Dual Camera



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RoHS

- This product does not contain any hazardous substances prohibited by the RoHS Directive.

WARNING

- You are requested to use RoHS compliant parts for maintenance or repair.
- You are requested to use lead-free solder.
(This product has been manufactured using lead-free solder. Be sure to follow the warning given on page 2 when carrying out repair work.)

CAUTION : Danger of explosion if battery is incorrectly replaced.

Replace only with the same or equivalent type recommended by the manufacturer.

Discard used batteries according to the manufacturer's instructions.

NOTE : 1. Parts order must contain model number, part number, and description.
2. Substitute parts may be supplied as the service parts.
3. N. S. P. : Not available as service parts.

Design and specification are subject to change without notice.

VPC-TH1

(Product Code : 168 173 02)
(U.S.A.) (Canada) (Taiwan) (General)

VPC-TH1EX

(Product Code : 168 173 03)
(Europe) (U.K.) (South America)
(China) (Australia) (Hong Kong)
(Russia) (Middle East) (Africa)
(General) (Korea) (Taiwan)

VPC-TH1GX

(Product Code : 168 173 04)
(South America) (China)
(Australia) (Hong Kong)
(General) (Korea) (Taiwan)

VPC-TH1R

(Product Code : 168 173 06)
(U.S.A.) (Canada) (Taiwan) (General)

VPC-TH1EXR

(Product Code : 168 173 07)
(Europe) (U.K.) (South America)
(China) (Australia) (Hong Kong)
(Russia) (Middle East) (Africa)
(General) (Korea) (Taiwan)

VPC-TH1GXR

(Product Code : 168 173 08)
(South America) (China)
(Australia) (Hong Kong)
(General) (Korea) (Taiwan)

VPC-TH1BL

(Product Code : 168 173 10)
(U.S.A.) (Canada) (Taiwan) (General)

VPC-TH1EXBL

(Product Code : 168 173 11)
(Europe) (U.K.) (South America)
(China) (Australia) (Hong Kong)
(Russia) (Middle East) (Africa)
(General) (Korea) (Taiwan)


VPC-TH1GXBL

(Product Code : 168 173 12)
(South America) (China)
(Australia) (Hong Kong)
(General) (Korea) (Taiwan)

VPC-ZH1R

(Product Code : 168 173 13)
(U.S.A.) (Canada)

PRODUCT SAFETY NOTICE

The components designated by a symbol () in this schematic diagram designates components whose value are of special significance to product safety. Should any component designated by a symbol need to be replaced, use only the part designated in the Parts List. Do not deviate from the resistance, wattage, and voltage ratings shown.

WARNING

Do not use solder containing lead.

This product has been manufactured using lead-free solder in order to help preserve the environment.

Because of this, be sure to use lead-free solder when carrying out repair work, and never use solder containing lead.

Lead-free solder has a melting point that is 30 - 40°C (86 - 104°F) higher than solder containing lead, and moreover it does not contain lead which attaches easily to other metals. As a result, it does not melt as easily as solder containing lead, and soldering will be more difficult even if the temperature of the soldering iron is increased.

The extra difficulty in soldering means that soldering time will increase and damage to the components or the circuit board may easily occur.

Because of this, you should use a soldering iron and solder that satisfy the following conditions when carrying out repair work.

Soldering iron

Use a soldering iron which is 70 W or equivalent, and which lets you adjust the tip temperature up to 450°C (842°F). It should also have as good temperature recovery characteristics as possible.

Set the temperature to 350°C (662°F) or less for chip components, to 380°C (716°F) for lead wires and similar, and to 420°C (788°F) when installing and removing shield plates.

The tip of the soldering iron should have a C-cut shape or a driver shape so that it can contact the circuit board as flat or in a line as much as possible.

Solder

Use solder with the metal content and composition ratio by weight given in the table below. Do not use solders which do not meet these conditions.

Metal content	Tin (Sn)	Silver (Ag)	Copper (Cu)
Composition ratio by weight	96.5 %	3.0 %	0.5 %

Lead-free solder is available for purchase as a service tool.

Use the following part number when ordering:

Part name: Lead-free solder with resin (0.5 mm dia., 500 g)

Part number: VJ8-0270

Note:

If replacing existing solder containing lead with lead-free solder in the soldered parts of products that have been manufactured up until now, remove all of the existing solder at those parts before applying the lead-free solder.

1. OUTLINE OF CIRCUIT DESCRIPTION

1-1. CMOS CIRCUIT DESCRIPTION

1. IC Configuration

The CMOS peripheral circuit block basically consists of the following ICs.

IC911 (MT9J001112STCV)

CMOS imager

CDS, AGC, ADC built-in

H driver, V driver, serial communication circuit built-in

2. IC911 (CMOS)

[Structure]

The electric charges which are generated when each pixel is optically converted are in turn converted into signal voltages by the FD amplifier, and they are then transmitted by the built-in H driver and V driver. The signals are sampled and amplified by the CDS and PGA circuits at the point they are output, and then they are AD converted and output. The output uses the 12 bit LVDS interface.

1/2.3-inch positive pixel array CMOS-type fixed imaging element

Effective pixels	3856 (H) X 2764 (V)
------------------	---------------------

1-2. CP1 and VF1 CIRCUIT DESCRIPTION

1. Circuit Description

1-1. Digital clamp

The optical black section of the extracts averaged values from the subsequent data to make the black level of the output data uniform for each line. The optical black section averaged value for each line is taken as the sum of the value for the previous line multiplied by the coefficient k and the value for the current line multiplied by the coefficient $1-k$.

1-2. Signal processor

1. γ correction circuit

This circuit performs (gamma) correction in order to maintain a linear relationship between the light input to the camera and the light output from the picture screen.

2. Color generation circuit

This circuit converts the image sensor into RGB signals.

3. Matrix circuit

This circuit generates the Y signals, R-Y signals and B-Y signals from the RGB signals.

4. Horizontal and vertical aperture circuit

This circuit is used generate the aperture signal.

1-3. AE/AWB and AF computing circuit

The AE/AWB carries out computation based on a 64-segment screen, and the AF carries out computations based on a 6-segment screen.

1-4. SDRAM controller

This circuit outputs address, RAS, CAS and CS data for controlling the SDRAM. It also refreshes the SDRAM.

1-5. Communication control

1. SDIO

This is the interface for the 8-bit microprocessor.

1-6. Digital encorder

It generates chroma signal from color difference signal.

2. Outline of Operation

When the shutter opens, the reset signals (ASIC and CPU) and the serial signals ("take a picture" commands) from the 8-bit microprocessor are input and operation starts.

The picture data from CMOS passes through the A/D and CDS, and is then input to the ASIC as digital data. The AF, AE, AWB, shutter, and AGC value are computed from this data, and three exposures are made to obtain the optimum picture. The data which has already been stored in the SDRAM is read by the CPU and color generation is carried out. Each pixel is interpolated from the surrounding data as being either R, G, and B primary color data to produce R, G and B data. At this time, correction of the lens distortion which is a characteristic of wide-angle lenses is carried out. After AWB and γ processing are carried out, a matrix is generated and aperture correction is carried out for the Y signal, and the data is then compressed by JPEG and is then written to card memory (SD card).

When the data is to be output to an external device, it is taken data from the memory and output via the USB I/F. When played back on the LCD and monitor, data is transferred from memory to the SDRAM, and the image is then elongated so that it is displayed over the SDRAM display area.

3. LCD Block

The LCD display circuit is located on the CP1 board and VF1 board, and consists of components such as a power circuit. The signals from the ASIC are 8-bit digital signals, that is input to the LCD directly. The 8-bit digital signals are converted to RGB signals inside the LCD driver circuit. This LCD has a 3-wire serial, and functions such as the brightness and image quality are controlled.

Because the LCD closes more as the difference in potential between the VCOM (common polar voltage: AC) and the R, G and B signals becomes greater, the display becomes darker; if the difference in potential is smaller, the element opens and the LCD become brighter.

In addition, the timing pulses for signals other than the video signals are also input from the ASIC directory to the LCD.

4. Lens drive block

4-1. Focus drive

The 16-bit serial data signals (LENS_SDI) and (LENS_SCLK and LENS_EN) which are output from the ASIC (IC101) are used to drive (FOCUS A +, FOCUS A -, FOCUS B + and FOCUS B -) by the motor driver IC (IC951), and are then used to microstep-drive the stepping motor for focusing operation. Detection of the standard focusing positions is carried out by means of the photointerruptor (F_SENSE) inside the lens block.

4-2. Zoom drive

The 16-bit serial data signals (LENS_SDI) and (LENS_SCLK and LENS_EN) which are output from the ASIC (IC101) are used to drive (ZOOM A +, ZOOM A -, ZOOM B + and ZOOM B -) by the motor driver IC (IC951), and are then used to microstep-drive the stepping motor for zooming operation. Detection of the standard zooming positions is carried out by means of the photointerruptor (F_SENSE) inside the lens block.

4-3. Iris drive

The drive method is a galvanometer type without braking coil. The output from the Hall sensor inside the lens is amplified by the Hall amplifier circuit inside the IC951 lens drive IC, and the difference between the current and target aperture determined by the resulting output and the exposure amount (16 bit serial signal (LENS_SDI) and (LENS_SCLK and LENS_EN)) output from the ASIC (IC101) is input to the servo amplifier circuit (IC951) to keep the aperture automatically controlled (DRIVE+ and DRIVE -) to the target aperture.

4-4. Shutter drive

Reverse voltage is applied to the above aperture drive coil to operate the shutter. When the shutter operates, the SHUTTER + signal that is output from the ASIC (IC101) becomes high (input to SHUTTER of IC951) and the shutter operates.

5. Video Clip Recording and Playback

5-1. Recording

The signal from the camera block is input to IC101 (ASIC). The data that is input to the ASIC is input to SDRAM, and converts this data to encoded MPEG4 data, after which it is written in sequence onto the SD card as streaming data. At this time, the audio signals that are input to the built-in microphone are converted into digital data by the audio CODEC IC of IC183, and they are then input to ASIC. The audio data is then encoded (AAC), and then it is written in sequence onto the SD card together as streaming data with the image signals described above.

5-2. Playback

The data is read from the SD card, and the encoded data is decoded into image data where it is displayed by the LCD or on a TV monitor. At the same time, the audio data is also decoded, and is input to IC182 as digital data. D/A conversion is carried out at IC182, and the sound is then output to the speaker or to the LINE OUT terminal.

6. Audio CODEC Circuit (IC182)

The audio signals from the microphone are converted into 16-bit digital data. AD conversion is carried out at a maximum sampling frequency of 48 kHz.

During audio playback, the 16-bit digital data is converted into analog signals and these drive headphone through the speaker or line out system and headphone amplifier. DA conversion is carried out at a maximum sampling frequency of 48 kHz.

1-3. PWA POWER CIRCUIT DESCRIPTION

1. Outline

This is the main power circuit, and is comprised of the following blocks.

Switching controller (IC501)

Motor system power output (L5301)

Digital 3.25 V power output (L5002)

Digital 1.2 V power output (L5003)

Backlight power output (Q5007, L5007)

Digital and CMOS 1.8 V power output (IC504, L5006)

CMOS analog 2.8 V power output (IC503, L5005)

2. Switching Controller (IC501)

This is the basic circuit which is necessary for controlling the power supply for a PWM-type switching regulator, and is provided with seven built-in channels, only CH1 (motor system), CH2 (digital 3.25 V), CH3 (digital 1.2 V) and CH7 (backlight) are used.

Each power supply output is received, and the PWM duty is varied so that each one is maintained at the correct voltage setting level.

Feedback for the backlight power (CH7) is provided to the both ends voltage of resistance so that regular current can be controlled to be current that was setting.

2-1. Short-circuit protection circuit

If output is short-circuited for the length of time determined by the condenser which is connected to Pin (A6) of IC501, all output is turned off. To reset, momentarily set the control signal (P ON) to repeat control, or temporarily disconnect the input power supply.

3. Motor System Power Output

BOOST 5 V is output. Feedback for the 5.0 V output is provided to the switching controller (Pin (B7) of IC501) so that PWM control can be carried out.

4. Digital 3.25 V Power Output

VDD3 is output. Feedback for the VDD3 is provided to the switching controller (Pin (F3) of IC501) so that PWM control can be carried out.

5. Digital 1.2 V Power Output

VDD 1.2 is output. Feedback for the 1.2 V is provided to the switching controller (Pin (C3) of IC501) so that PWM control to be carried out.

6. Backlight Power Supply output

Regular current is being transmitted to LED for LCD backlight. Feedback for the both ends voltage of resistance that is being positioned to in series LED are provided to the switching controller (Pin (C4) of IC501) so that PWM control to be carried out.

7. Digital and CMOS 1.8 V Power Output

VDD 1.8 is output. Feedback for the VDD 1.8 is provided to the switching controller (Pin (3) of IC504) so that PWM control to be carried out.

8. CMOS Analog 2.8 V Power Output

VAA 2.8 is output. Feedback for the VAA 2.8 is provided to the switching controller (Pin (3) of IC503) so that PWM control to be carried out.

1-4. ST1 STROBE CIRCUIT DESCRIPTION

1. Charging Circuit

When UNREG power is supplied to the charge circuit and the CHG signal from microprocessor becomes High (3.3 V), the charging circuit starts operating and the main electrolytic capacitor is charged with high-voltage direct current. However, when the CHG signal is Low (0 V), the charging circuit does not operate.

1-1. Charge switch

When the CHG signal switches to Hi, IC541 starts charging operation.

1-2. Power supply filter

C5401 constitutes the power supply filter. They smooth out ripples in the current which accompany the switching of the oscillation transformer.

1-3. Oscillation circuit

This circuit generates an AC voltage (pulse) in order to increase the UNREG power supply voltage when drops in current occur. This circuit generates a drive pulse with a frequency of approximately 200-300 kHz, and drive the oscillation transformer.

1-4. Oscillation transformer

The low-voltage alternating current which is generated by the oscillation control circuit is converted to a high-voltage alternating current by the oscillation transformer.

1-5. Rectifier circuit

The high-voltage alternating current which is generated at the secondary side of T5401 is rectified to produce a high-voltage direct current and is accumulated at electrolytic capacitor C5412.

1-6. Charge monitoring circuit

The functions programmed in the IC541 monitor oscillations and estimate the charging voltage. If the voltage exceeds the rated value, charging automatically stops. Then, the ZCHG_DONE signal is changed to Lo output and a "charging stopped" signal is sent to the microcomputer.

2. Light Emission Circuit

When FLCTL signal is input from the ASIC, the stroboscope emits light.

2-1. Emission control circuit

When the FLCTL signal is input to the emission control circuit, Q5402 switches on and preparation is made to the light emitting. Moreover, when a FLCTL signal becomes Lo, the stroboscope stops emitting light.

2-2. Trigger circuit

The Q5402 is turned ON by the FLCTL signal and light emission preparation is preformed. Simultaneously, high voltage pulses of several kV are emitted from the trigger coil and applied to the light emitter.

2-3. Light emitting element

When the high-voltage pulse from the trigger circuit is applied to the light emitting part, current flows to the light emitting element and light is emitted.

Beware of electric shocks.

1-5. SYA CIRCUIT DESCRIPTION

1. Configuration and Functions

For the overall configuration of the SYA block, refer to the block diagram. The SYA block centers around a 8-bit microprocessor (IC301), and controls camera system condition (mode).

The 8-bit microprocessor handles the following functions.

1. Operation key input, 2. Clock control and backup, 3. Power ON/OFF, 4. Strobe charge control

Pin	Signal	I/O	Outline
1	ASIC_SCK	O	Serial clock output (CL required)
2	ZCARD	I	Card detection (SW3.2 V required)
3	ZBACKUPCTL	O	Backup battery charge control
4	CHG_CNT	O	Camera charge permission
5	HOT_LINE	I	Hot line request from ASIC
6	GREEN_LED	O	Switch unit LED (green) (H= lighting)
7	RED_LED	O	Switch unit LED (red) (H= lighting)/ combine with UTX (CL required)
8	ST_CHG_ON	O	Strobe charge control (H= charge)
9	VDD2	-	-
10	VSS2	-	-
11~14	SCAN IN4~1	I	Keyscan input 4~1
15	ZUSB_DET	I	USB power detection terminal (L= detection)
16	HDMI_HPD	I	HDMI hot plug detection
17	ZCHG_DONE	I	Main condensor charge voltage detection
18	TIMEOUT	I	Charge done detection
19	BAT_UTX	O	Battery power detection IC UART sending
20	BAT_URX	I	Battery power detection IC UART receiving
21	SCAN_IN0	I	Keyscan input 0
22	PANEL_OPEN	I	Panel open detection (MR sensor)
23	KEY 2nd	I	S2 key input
24	USB_ON	O	USB charge ON/OFF
25	NOT USED	I	(HDMI_INT delete)
26	NOT USED	O	(TGVD delete)
27	MRST	O	System reset (MRST)
28	SW3.2ON	O	SW 3.2 V power (L= 3.2 V)
29	PON2	O	Digital system power start-up signal
30	NOT USED	I	(I2CSDATA delete)
31	P ON	O	Digital system power start-up signal
32	NAND_RESET	O	OneNAND reset
33	PLLEN	O	PLL enable signal
34	ERR	I	Charge error detection
35	VSS3	-	-
36	VDD3	-	-
37	RDSEL	I	Debugger select terminal
38	CLK (SFW)	I	Debug CN
39	DATA0 (SFW)	I	Debug CN
40	DC_IN	I	DC jack insertion detection (SW3.2 V required)
41	HINGE	I	Panel rotation detection
42~44	SCAN OUT2~0	O	Keyscan output 2~0
45	ZOOM_SW_AD	I	Zoom key AD input
46	NOT USED	-	-
47	ZAV_JACK	I	Cable detection

See next page →

48	BAT_TMP	I	Battery temperature detection
49	BAT_OFF	I	Battery OFF detection signal input
50	ZSREQ	I	Serial communication request signal (CL required)
51	KEY_1st	I	S1 key input
52	ZBOOT_COMREQ	I/O	ZBOOT output
53	ZRESET	I	SBM reset input
54	XCIN	I	32 k oscillation input
55	XCOUT	O	32 k oscillation output
56	VSS1	-	-
57	XIN	I	4M oscillation input
58	XOUT	O	4M oscillation output
59	VDD1	-	-
60	BATTERY	I	UNREG voltage detection
61	NOT USED	-	-
62	INT_TEMP	I	Camera temperature detection
63	ASIC_SDI	O	Serial data output (CL required)
64	ASIC_SDO	I	Serial data input (CL required)

Table 5-1. 8-bit Microprocessor Port Specification

2. Internal Communication Bus

The SYA block carries out overall control of camera operation by detecting the input from the keyboard and the condition of the camera circuits. The 8-bit microprocessor reads the signals from each sensor element as input data and outputs this data to the camera circuits (ASIC) or to the LCD display device as operation mode setting data. Fig. 5-1 shows the internal communication between the 8-bit microprocessor, ASIC and SPARC lite circuits.

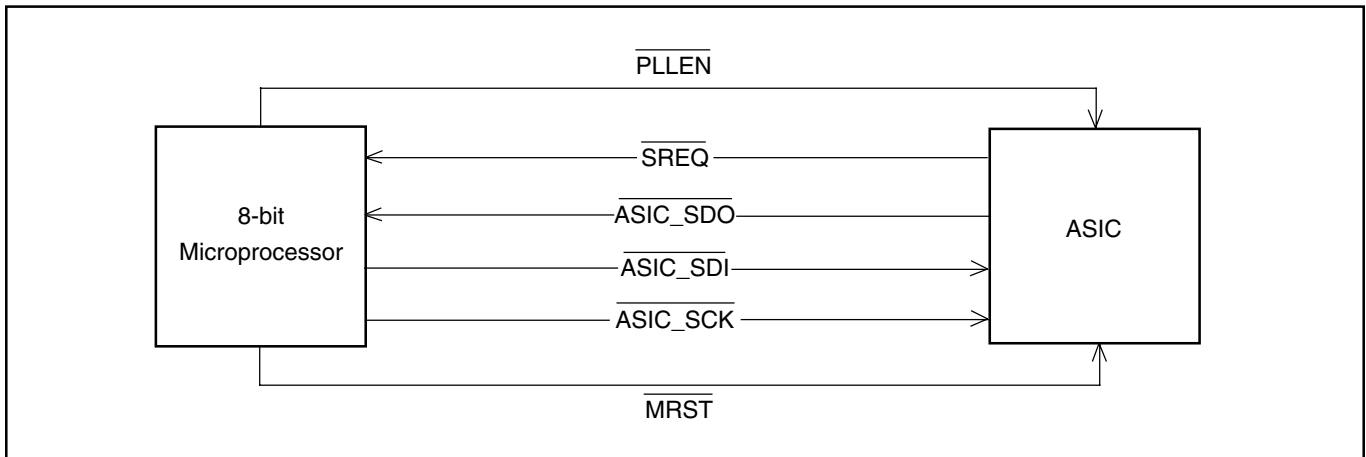


Fig. 5-1 Internal Bus Communication System

3. Key Operaiton

For details of the key operation, refer to the instruction manual.

SCAN OUT \ SCAN IN	0	1	2	3	4
0	UP	DOWN	LEFT	RIGHT	SET
1	-	VREC	PLAY	MENU	POWER
2	PW_TEST	-	TEST	-	-

Table 5-2. Key Operation

4. Power Supply Control

The 8-bit microprocessor controls the power supply for the overall system.

The following is a description of how the power supply is turned on and off. When the battery is attached or DC IN input, a regulated 3.2 V (power off: 2.4 V) voltage is normally input to the 8-bit microprocessor (IC301) by IC302, so that clock counting and key scanning is carried out even when the power switch is turned off, so that the camera can start up again. When the battery is removed and DC IN does not input, the 8-bit microprocessor operates in sleep mode using the backup battery. At this time, the 8-bit microprocessor only carries out clock counting, and waits in standby for the battery to be attached again or DC IN input. When a switch is operated, the 8-bit microprocessor supplies power to the system as required.

The 8-bit microprocessor first set the P ON signal at pin (31) and the P ON2 signal at pin (29) to high, and then turns on the DC/DC converter. After this, low signal is output from pin (27) so that the ASIC is set to the reset condition. After this these pins set to high, and set to active condition. Once it is completed, the ASIC returns to the reset condition, all DC/DC converters are turned off and the power supply to the whole system is halted.

		ASIC, memory	CMOS	8 bit CPU
Power voltage		3.3 V 1.0 V 1.8 V	2.8 V (A) 2.8 V (D), 1.8 V (D)	3.2 V
Power OFF		OFF	OFF	32KHz
CAMERA	Power switch ON - Auto power OFF	OFF	OFF	32KHz
	LCD finder	ON	ON	4 MHz
Play back		ON	OFF	4 MHz

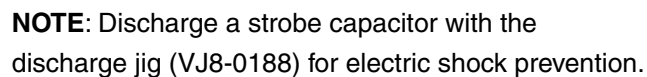
Table 5-3. Camera Mode

Note) 4 MHz = Main clock operation, 32 kHz = Sub clock operation

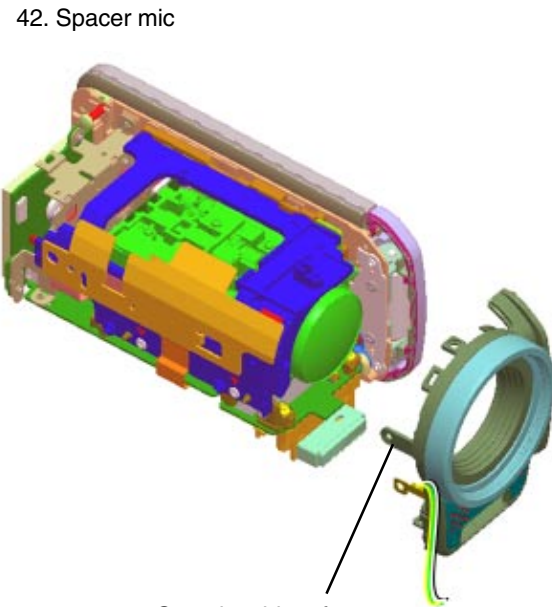
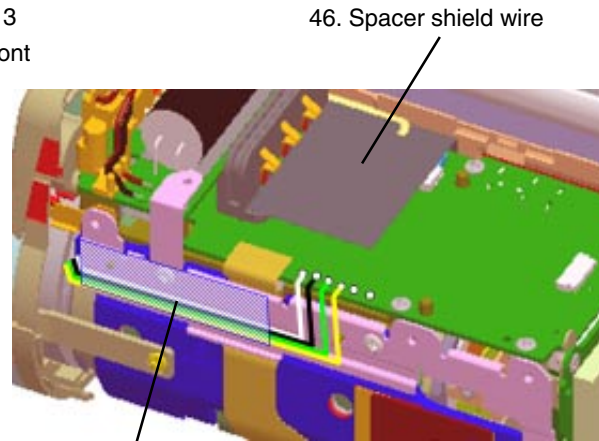
MEMO

Handwriting practice lines consisting of 20 horizontal dashed lines.

2-1. REMOVAL OF CABINET BOTTOM, CABINET TOP, CABINET BACK, TB4 BOARD AND CABINET FRONT



1. Cover battery
2. Spacer bottom
3. Spacer LCD
4. Spacer LCD front
5. Screw 1.7 x 7
6. Three screws 1.7 x 3
7. Screw 1.7 x 3
8. Three screws 1.7 x 4
9. Remove the cabi bottom from the main body.
10. Screw 1.7 x 3
11. Holder strap front
12. Spacer blind
13. Screw 1.7 x 3
14. Holder strap back
15. Two screws 1.7 x 4
16. Stand
17. Remove the solder.
18. Screw 1.7 x 3
19. Screw 1.7 x 3
20. Cabinet top
21. Spacer cabi front
22. Flexible pwb CP1 & TB4
23. Cover SD
24. Screw 1.7 x 3
25. Two screws 1.7 x 3
26. Two screws 1.7 x 3
27. Remove the cabinet back from the main body.
28. Cover DC
29. Three screws 1.7 x 4
30. Holder back
31. Two screws 1.7 x 4
32. TB4 board
33. FPC
34. Unit, zoom
35. Flexible pwb CP1 & TB4
36. Button select
37. Holder button bas
38. Button menu
39. Button rec play
40. Button movie
41. Button shutter
42. Spacer mic
43. Remove the solder.
44. Two screws 1.7 x 4
45. Holder bottom
46. Spacer shield wire
47. Connector
48. Two screws 1.7 x 2
49. Dec joint
50. Two screws 1.7 x 4
51. Screw 1.7 x 3
52. Two screws 1.7 x 3
53. Compl, cabinet front
54. Screw 1.7 x 3
55. Screw 1.7 x 3

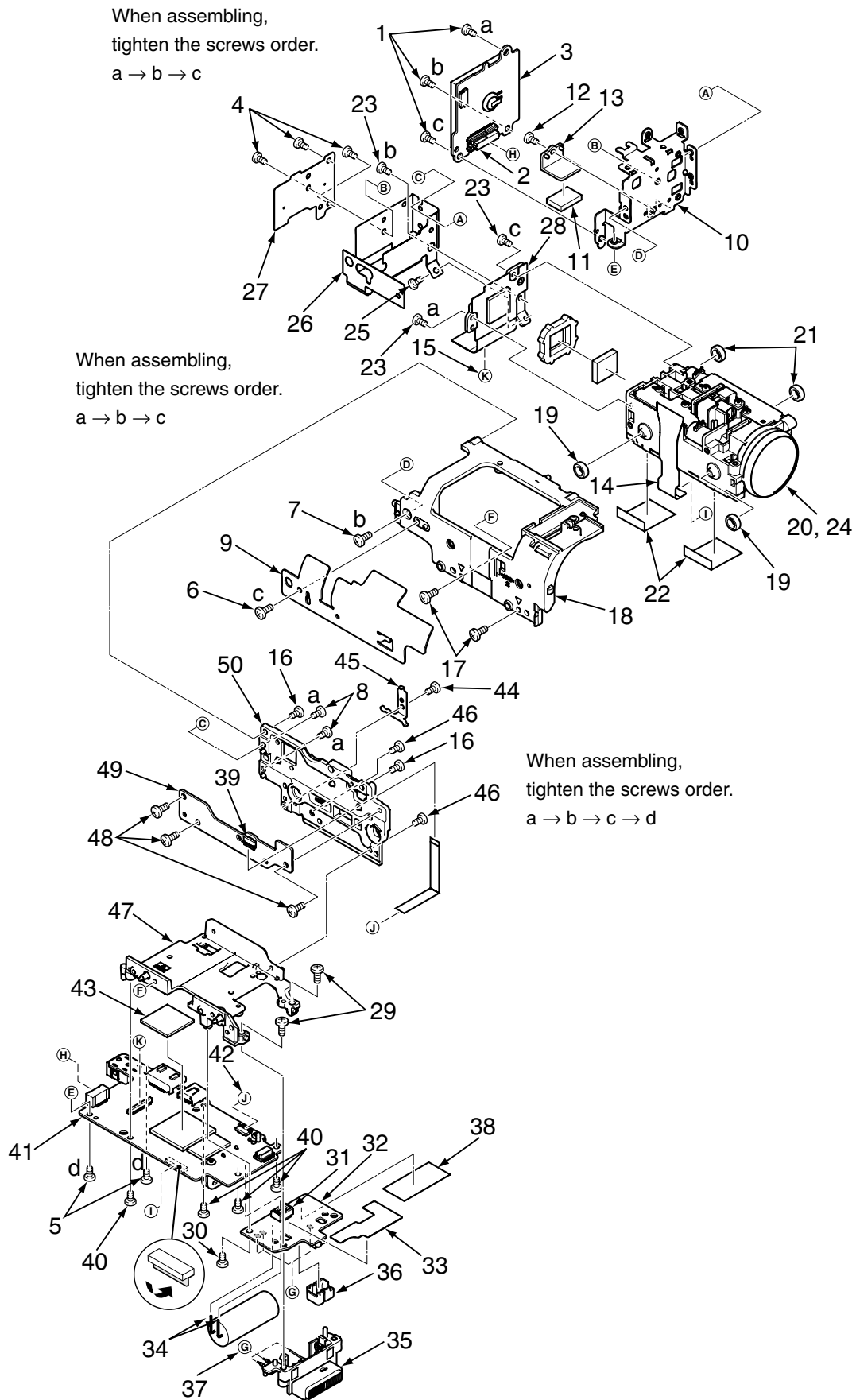


53. Compl, cabinet front



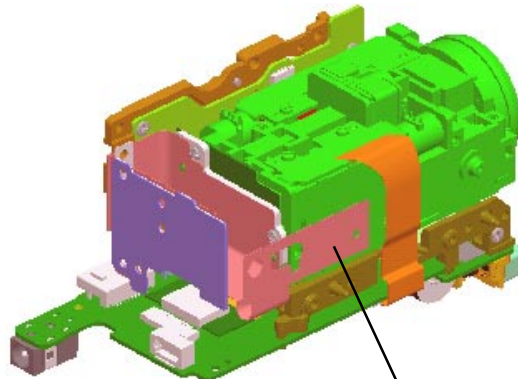
Note:
Do not tuck the
lead wires.

2-2. REMOVAL OF TB1 BOARD, LENS, ST1 BOARD, CP1 BOARD AND TB3 BOARD



1. Three screws 1.7 x 3
2. Connector
3. TB1 board
4. Three screws 1.7 x 2.5
5. Two screws 1.7 x 3
6. Screw 1.7 x 4
7. Screw 1.7 x 3
8. Two screws 1.7 x 3
9. Heat sink CMOS
10. Holder TB1
11. Spacer CA
12. Screw 1.7 x 2.5
13. Holder CA
14. FPC
15. Connector

48. Three screws 1.7 x 2.5
49. TB3 board
50. Chassis right



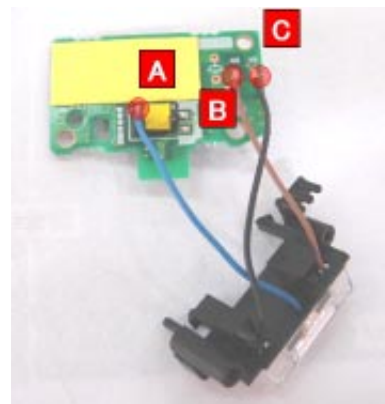
26. Heat sink tape CMOS

35. Assy lamp dressing method

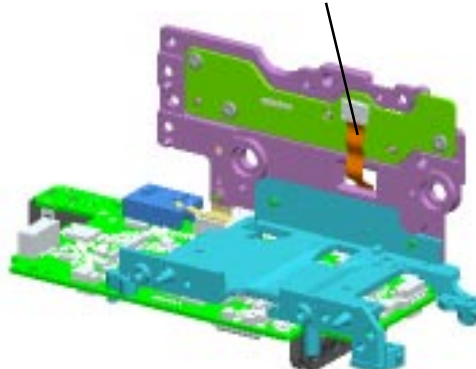


16. Two screws 1.7 x 4
17. Two screws 1.7 x 4
18. Holder lens chassis
19. Holder lens
20. Remove the lens part.
21. Holder lens
22. Spacer lens bottom
23. Three screws 1.4 x 3.5
24. Lens
25. Screw 1.7 x 2
26. Heat sink tape CMOS
27. Holder heat CMOS TB1
28. Assy, flexible pwb CA1 + mounting lens
29. Two screws 1.7 x 7
30. Screw 1.7 x 3
31. Connector
32. ST1 board
33. Spacer ST1
34. Remove the solder.
35. Assy, lamp
36. Cover trigger
37. Remove the solder.
38. Spacer con ST1
39. Flexible pwb CP1 & TB3
40. Four screws 1.7 x 3
41. CP1 board
42. Flexible pwb CP1 & TB3
43. Heat sink rub ASIC
44. Screw 1.4 x 2
45. Earth jack
46. Two screws 1.7 x 3
47. Chassis bottom

35. Assy lamp soldering order



39, 42. Flexible pwb CP1 & TB3



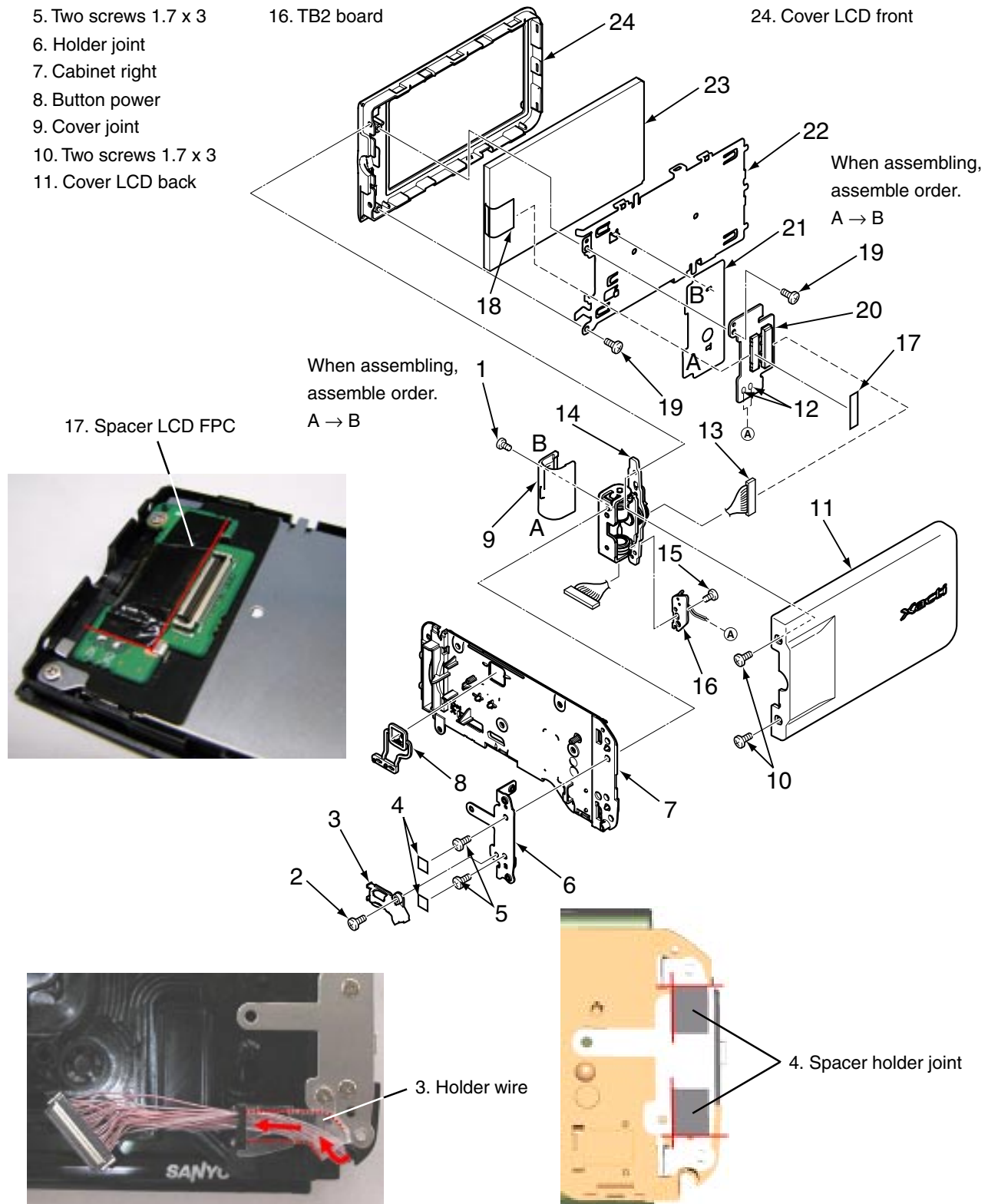
2-3. REMOVAL OF TB2 BOARD, VF1 BOARD AND LCD

1. Screw 1.7 x 2
2. Screw 1.7 x 3
3. Holder wire
4. Spacer holder joint
5. Two screws 1.7 x 3
6. Holder joint
7. Cabinet right
8. Button power
9. Cover joint
10. Two screws 1.7 x 3
11. Cover LCD back

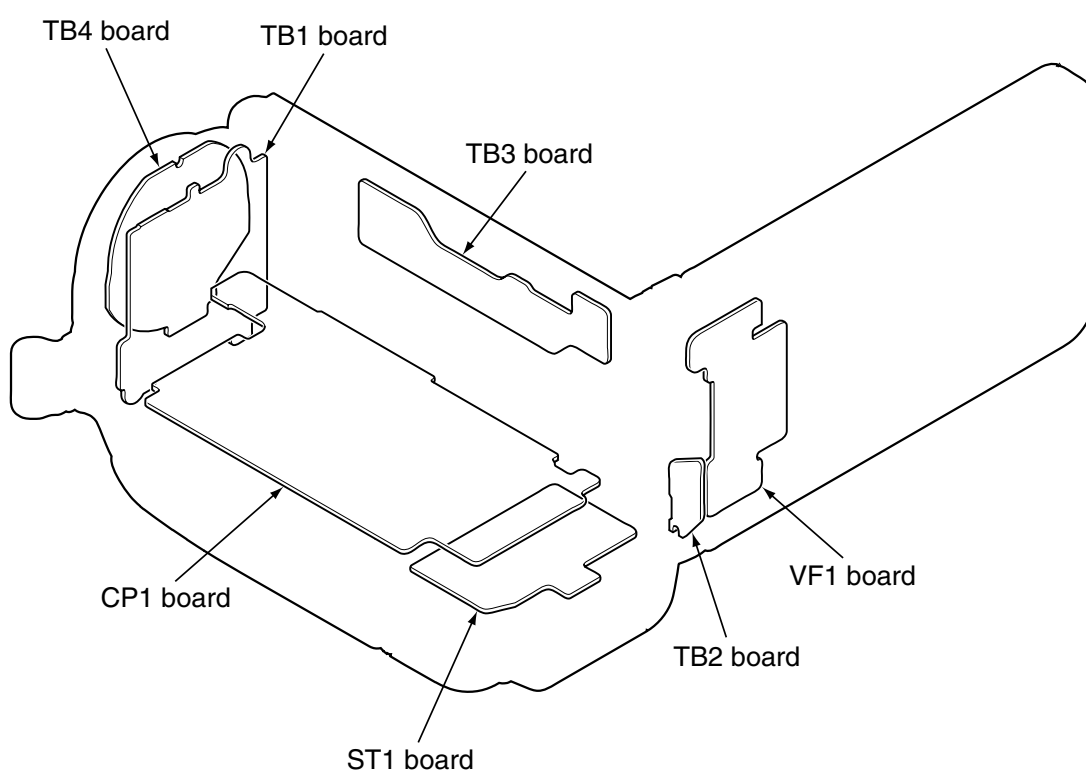
12. Remove the solder.
13. Connector
14. Assy, joint
15. Screw 1.7 x 2
16. TB2 board

17. Spacer LCD FPC
18. FPC
19. Two screws 1.7 x 3

20. VF1 board
21. Spacer pwb
22. Holder LCD
23. LCD
24. Cover LCD front



2-4. BOARD LOCATION



3. ELECTRICAL ADJUSTMENT

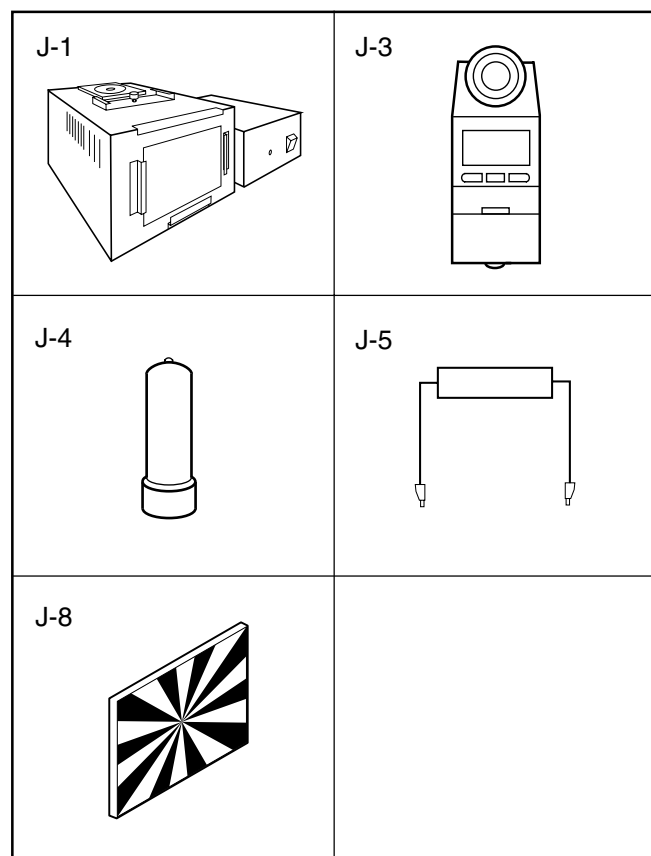
3-1. Table for Servicing Tools

Ref. No.	Name	Number	Part code
J-1	Pattern box	1	VJ8-0190
J-2	Calibration software	1	
J-3	Chroma meter	1	VJ8-0192
J-4	Spare lump (pattern box)	1	VJ8-0191
J-5	Discharge jig	1	VJ8-0188
J-6	Collimator	1	VJ8-0260
J-7	Spare lump (collimator)	1	VJ8-0282
J-8	Siemens star chart	1	
J-9	Fluorescent tube viewer	1	

J-9: Fluorescent tube viewer: HAKUBA light viewer 5700

Download the calibration software and the firmware from the following URL.

<http://www.digital-sanyo.com/overseas/service/>
Place the DscCalDi.exe file, camapi32.dll file and QrCodeInfo.dll file together into a folder of your choice.



3-2. Equipment

1. AC adaptor
2. PC (IBM®-compatible PC, Windows 2000 or XP or Vista)

3-3. Adjustment Items and Order

1. Optical Axis Adjustment
2. Lens Adjustment (Infinity)
3. Lens Adjustment (1m)
4. AWB Adjustment
5. CMOS White Point Defect Detect Adjustment
6. CMOS Black Point And White Point Defect Detect Adjustment In Lighted

Note: If the lens, board and changing the part, it is necessary to adjust again. Item 1-6 adjustments should be carried out in sequence.

*Adjustment environment

Temperature: 25 ± 10 degrees, Humidity: 55 ± 25 %

3-4. Setup

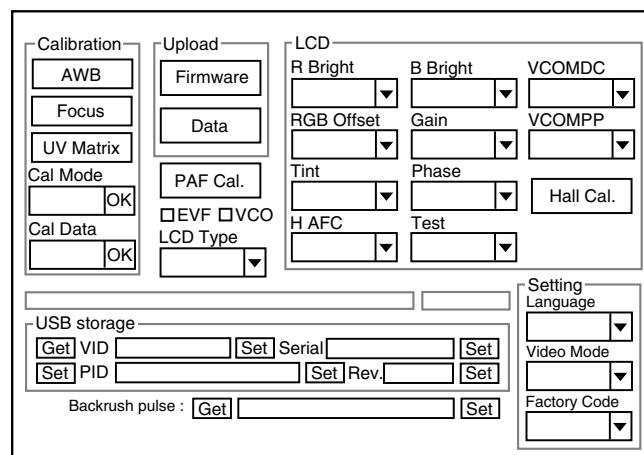
1. System requirements

- Windows 2000 or XP or Vista
- IBM®-compatible PC with pentium processor
- USB port
- 40 MB RAM
- Hard disk drive with at least 15 MB available
- VGA or SVGA monitor with at least 256-color display

2. Pattern box

Turn on the switch and wait for 30 minutes for aging to take place before using Color Pure. It is used after adjusting the chroma meter (VJ8-0192) adjust color temperature to 3100 ± 20 K and luminosity to 900 ± 20 cd/m². Be careful of handling the lump and its circumference are high temperature during use and after power off for a while.

3. Computer screen during adjustment



3-5. Connecting the camera to the computer

1. Use the supplied dedicated USB interface cable to connect the camera to the computer.
2. Turn on the camera.
3. Choose the "COMPUTER", and press the SET button. Next, choose the "CARD READER", and press the SET button.

3-6. The adjustment item which is necessary in part exchange

	Optical Axis Adjustment	Lens Adjustment (Infinity)	Lens Adjustment (1 m)	AWB Adjustment	CMOS White Point Defect Detect Adjustment	CMOS Black Point And White Point Defect Detect Adjustment In Lighted	Factory Cord Setting	Language Setting	USB storage information registration	Reset Setting
COMPL PWB CP1	○	○	○	○	○	○	○	△	○	○
COMPL PWB VF1										
COMPL PWB ST1										
COMPL PWB TB1										
COMPL PWB TB2										
COMPL PWB TB3										
COMPL PWB TB4										
ASSY, FLEXIBLE PWB CA1	○	○	○	○	○	○				

○ : Be sure to carry out the necessary adjustments after replacing the unit.

△ : Adjustment is possible from the menu setting screen of the camera and by using the calibration software.

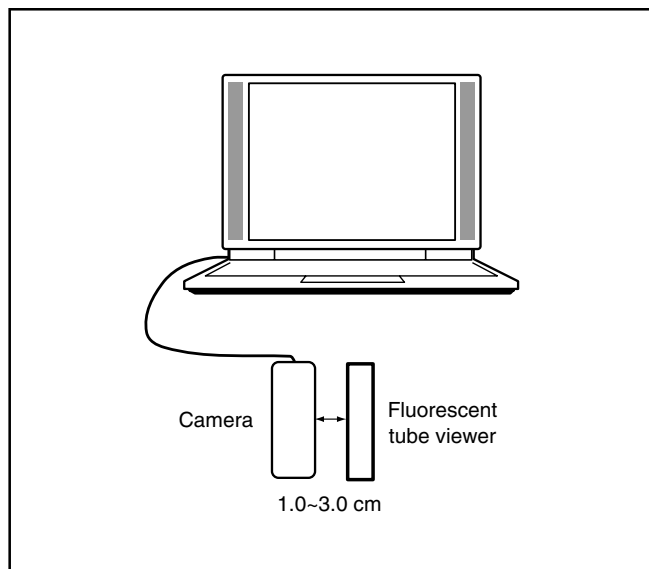
3-7. Updating the firmware

Check the firmware version immediately after the CP1 board has been replaced. If an old version is being used, interference and errors in operation may also occur. If an old version is being used, update it with a newer version.

Refer to 3-13. Firmware uploading procedure. (Page 23)

3-8. Adjust Specifications

1. Optical Axis Adjustment



Preparation:

POWER switch: ON

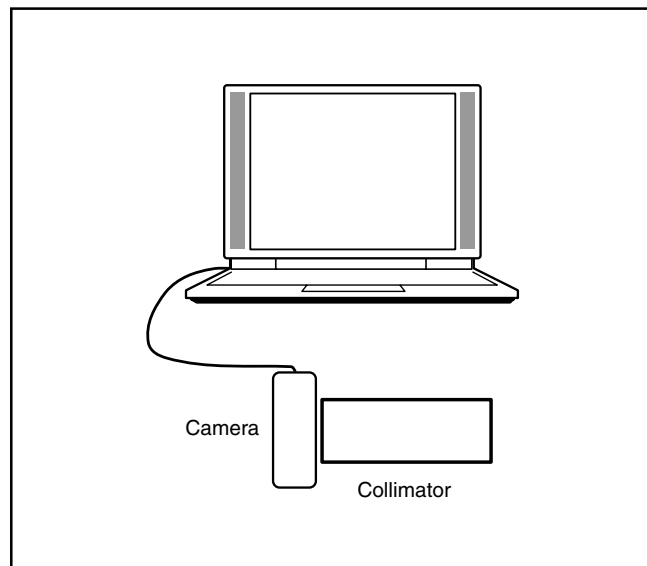
Note:

Do not vibrate during the adjustment.

Adjustment method:

1. Set a distance of 1.0-3.0 cm between the camera lens and the white part of fluorescent tube viewer.
(Do not enter any light.)
2. Double-click on the DscCalDi.exe.
3. Input "251" to the "CalMode", and click the OK.
4. Adjustment value will appear on the screen.
5. Click the OK.

2. Lens Adjustment (Infinity)



Preparation:

POWER switch: ON

If using a ready-made collimator, set to infinity.

Note:

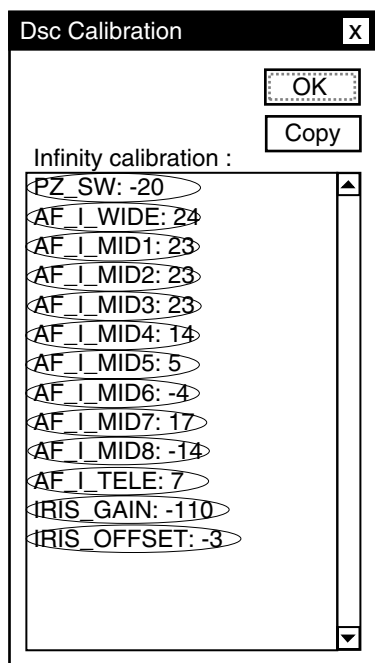
Do not vibrate during the adjustment.

If readjusting after it has already been adjusted, wait for 15 minutes or more for the unit to cool down first.

Adjustment method:

1. Set the camera so that it becomes center of the siemens star chart in the collimator (zoom wide and tele).
(Set a distance of 0.5-1.0 cm between camera lens and collimator lens. Do not touch the each lens.)
2. Set the camera so that it becomes center of the screen in the collimator.
3. Double-click on the DscCalDi.exe.
4. Select "Infinity Cal." on the LCD "Test", and click the "Yes".
5. Lens infinity adjustment value will appear on the screen.
6. Click the OK.

3. Lens Adjustment (1m) is carried out after this adjustment.



Adjustment value determination is effectuated using below values.

The adjustment values fulfill the conditions below, they are determined as within specifications.

Adjustment value determination

PZ_SW: ZSW

ZSW: adjustment value of zoom PI switch position
($-52 \leq ZSW \leq 34$)

AF_I_WIDE: ZIW

ZIW: infinity adjustment value of focus at zoom position wide
($-77 \leq ZIW \leq 78$)

AF_I_MID1: ZIM1

ZIM1: infinity adjustment value of focus at zoom position middle1
($-96 \leq ZIM1 \leq 96$)

AF_I_MID2: ZIM2

ZIM2: infinity adjustment value of focus at zoom position middle2
($-115 \leq ZIM2 \leq 114$)

AF_I_MID3: ZIM3

ZIM3: infinity adjustment value of focus at zoom position middle3
($-138 \leq ZIM3 \leq 137$)

AF_I_MID4: ZIM4

ZIM4: infinity adjustment value of focus at zoom position middle4
($-194 \leq ZIM4 \leq 195$)

AF_I_MID5: ZIM5

ZIM5: infinity adjustment value of focus at zoom position middle5
($-237 \leq ZIM5 \leq 238$)

AF_I_MID6: ZIM6

ZIM6: infinity adjustment value of focus at zoom position middle6
($-288 \leq ZIM6 \leq 287$)

AF_I_MID7: ZIM7

ZIM7: infinity adjustment value of focus at zoom position middle7
($-348 \leq ZIM7 \leq 348$)

AF_I_MID8: ZIM8

ZIM8: infinity adjustment value of focus at zoom position middle8
($-471 \leq ZIM8 \leq 470$)

AF_I_TELE: ZIT

ZIT: infinity adjustment value of focus at zoom position tele
($-200 \leq ZIT \leq 598$)

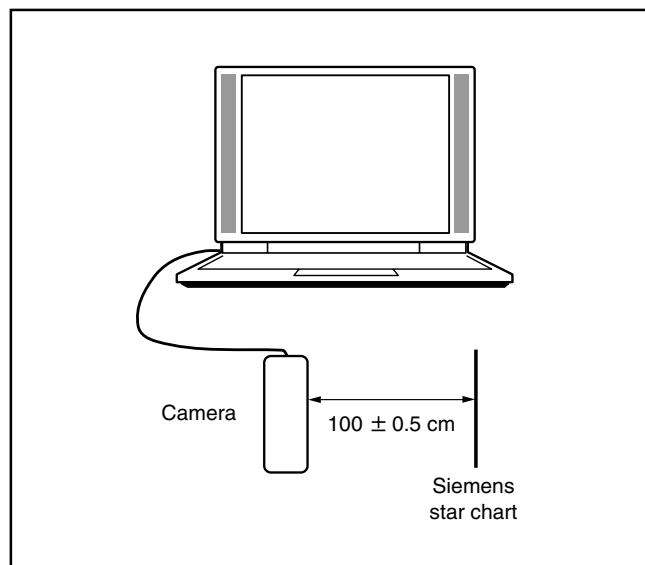
IRIS_GAIN: g

g: adjustment value of gain ($-128 \leq g \leq 127$)

IRIS_OFFSET: o

o: adjustment value of offset ($-128 \leq o \leq 127$)

3. Lens Adjustment (1m)

**Preparation:**

POWER switch: ON

Adjustment condition:

Siemens star chart (A3)

Fluorescent light illumination with no flicker

Illumination above the subject should be 700 lux \pm 10%.

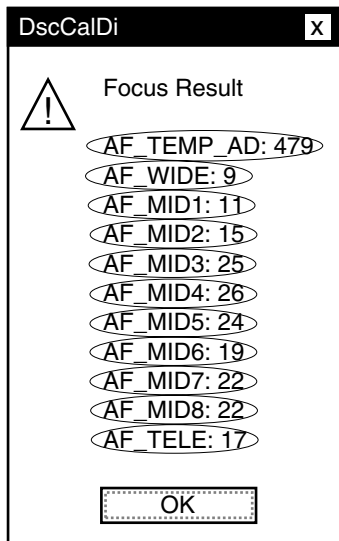
Note:

Do not vibrate during the adjustment.

If readjusting after it has already been adjusted, wait for 15 minutes or more for the unit to cool down first.

Adjustment method:

1. Set the siemens star chart 100 ± 0.5 cm from lens surface so that it becomes center of the screen (zoom wide and tele). Set the camera and the chart in a straight, and do not put optical systems (mirror and conversion lens etc.)
2. Double-click on the DscCalDi.exe.
3. Click the "Focus", and Click the "Yes".
4. Lens adjustment value will appear on the screen.
5. Click the OK.



Adjustment value determination is effectuated using below values.

The adjustment values fulfill the conditions below, they are determined as within specifications.

Adjustment value determination

AF_TEMP_AD: ATAD

ATAD: adjustment value of focus temperature A/D
($264 < \text{ATAD} < 837$)

AF_WIDE: ZW

ZW: adjustment value of focus at zoom position wide
($-77 \leq \text{ZW} \leq 78$)

AF_MID1: ZM1

ZM1: adjustment value of focus at zoom position middle1
($-96 \leq \text{ZM1} \leq 96$)

AF_MID2: ZM2

ZM2: adjustment value of focus at zoom position middle2
($-118 \leq \text{ZM2} \leq 117$)

AF_MID3: ZM3

ZM3: adjustment value of focus at zoom position middle3
($-147 \leq \text{ZM3} \leq 97$)

AF_MID4: ZM4

ZM4: adjustment value of focus at zoom position middle4
($-199 \leq \text{ZM4} \leq 148$)

AF_MID5: ZM5

ZM5: adjustment value of focus at zoom position middle5
($-234 \leq \text{ZM5} \leq 213$)

AF_MID6: ZM6

ZM6: adjustment value of focus at zoom position middle6
($-240 \leq \text{ZM6} \leq 241$)

AF_MID7: ZM7

ZM7: adjustment value of focus at zoom position middle7
($-259 \leq \text{ZM7} \leq 230$)

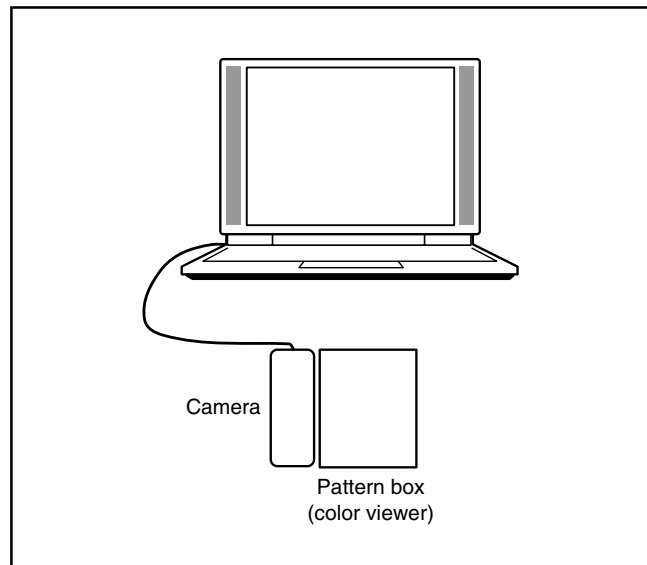
AF_MID8: ZM8

ZM8: adjustment value of focus at zoom position middle8
($-286 \leq \text{ZM8} \leq 286$)

AF_TELE: ZT

ZT: adjustment value of focus at zoom position tele
($-306 \leq \text{ZT} \leq 306$)

4. AWB Adjustment



Preparation:

POWER switch: ON

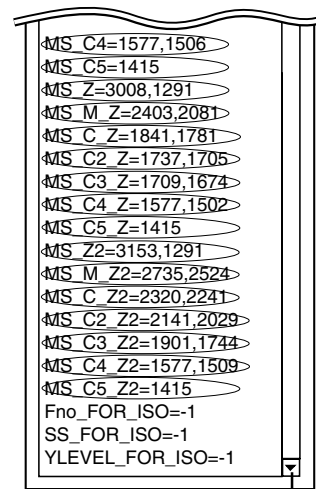
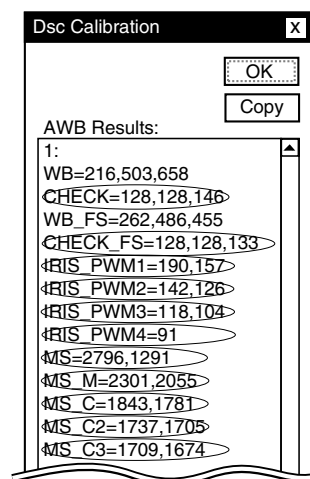
Setting of pattern box:

Color temperature: 3100 ± 20 (K)

Luminance: 900 ± 20 (cd/m²)

Adjusting method:

1. Set a distance of 0.5-1.0 cm between the pattern box and the camera. (Do not enter any light.)
2. Double-click on the DscCalDi.exe.
3. Click the AWB, and click the Yes.
4. AWB adjustment value will appear on the screen.
5. Click the OK.



When all of the AWB adjustment screen is not displayed, use a scroll bar.

Adjustment value determination is effectuated using the "CHECK", "CHECK_FS", "MS", "MS_M", "MS_C", "MS_C2", "MS_C3", "MS_C4", "MS_C5", "MS_Z", "MS_M_Z", "MS_C_Z", "MS_C2_Z", "MS_C3_Z", "MS_C4_Z", "MS_C5_Z", "MS_Z2", "MS_M_Z2", "MS_C_Z2", "MS_C2_Z2", "MS_C3_Z2", "MS_C4_Z2", "MS_C5_Z2", "IRIS_PWM1", "IRIS_PWM2", "IRIS_PWM3" and "IRIS_PWM4" values. If

CHECK = wc0, wc1, wc2

CHECK_FS = wnc0, wnc1, wnc2

MS = ms1, ms2

MS_M = ms3, ms4

MS_C = ms5, ms6

MS_C2 = ms7, ms8

MS_C3 = ms9, ms10

MS_C4 = ms11, ms12

MS_C5 = ms13

MS_Z = ms14, ms15

MS_M_Z = ms16, ms17

MS_C_Z = ms18, ms19

MS_C2_Z = ms20, ms21

MS_C3_Z = ms22, ms23

MS_C4_Z = ms24, ms25

MS_C5_Z = ms26

MS_Z2 = ms27, ms28

MS_M_Z2 = ms29, ms30

MS_C_Z2 = ms31, ms32

MS_C2_Z2 = ms33, ms34

MS_C3_Z2 = ms35, ms36

MS_C4_Z2 = ms37, ms38

MS_C5_Z2 = ms39

IRIS_PWM1 = s1, s2

IRIS_PWM2 = s3, s4

IRIS_PWM3 = s5, s6

IRIS_PWM4 = s7

the adjustment values fulfill the conditions below, they are determined as within specifications.

Adjustment value determination

wc0=128 ± 2, wc1=128 ± 2, wc2<=255

wnc0=128 ± 2, wnc1=128 ± 2, wnc2<=255

2090<=ms1<=3500, 990<=ms2<=1620,

1860<=ms3<=2730, 1680<=ms4<=2440,

1510<=ms5<=2210, 1430<=ms6<=2150,

1380<=ms7<=2100, 1370<=ms8<=2080,

1370<=ms9<=2080, 1350<=ms10<=2060,

1230<=ms11<=1940, 1150<=ms12<=1870,

1040<=ms13<=1760, 2400<=ms14<=3800,

990<=ms15<=1620, 1990<=ms16<=3000,

1730<=ms17<=2500, 1510<=ms18<=2210,

1430<=ms19<=2150, 1380<=ms20<=2100,

1370<=ms21<=2080, 1370<=ms22<=2080,

1350<=ms23<=2060, 1230<=ms24<=1940,

1150<=ms25<=1870, 1040<=ms26<=1760,

2400<=ms27<=3910, 990<=ms28<=1620,

2120<=ms29<=3320, 1970<=ms30<=3030,

1860<=ms31<=2780, 1820<=ms32<=2650,

1730<=ms33<=2560, 1640<=ms34<=2480,

1520<=ms35<=2360, 1360<=ms36<=2200,

1230<=ms37<=1940, 1150<=ms38<=1870,

1040<=ms39<=1760

s1>s2>s3>s4>s5>s6>s7

Adjustment values other than the above are irrelevant.

5. CMOS White Point Defect Detect Adjustment

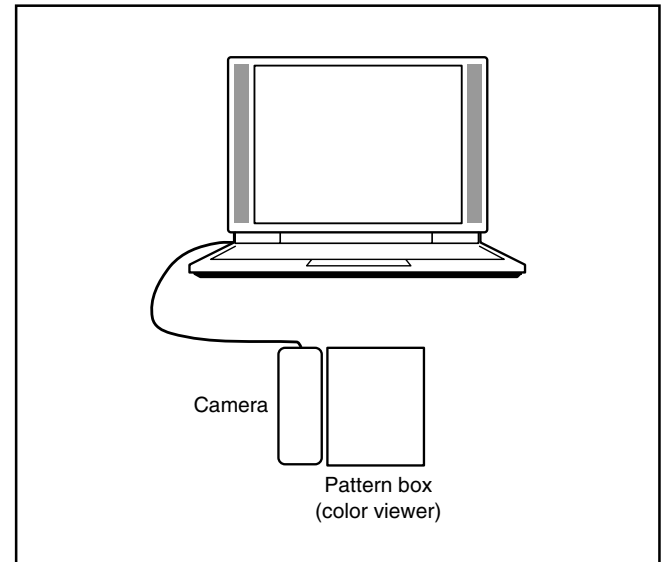
Preparation:

POWER switch: ON

Adjustment method:

1. Double-click on the DscCalDi.exe.
2. Select "CCD Defect" on the LCD "Test", and click the "Yes".
3. After the adjustment is completed, OK will display.
4. Click the OK.

6. CMOS Black Point And White Point Defect Detect Adjustment In Lighted



Preparation:

POWER switch: ON

Setting of pattern box:

Color temperature: 3100 ± 20 (K)

Luminance: 900 ± 20 (cd/m²)

Adjusting method:

1. Set a distance of 0.5-1.0 cm between the pattern box and the camera.
2. Double-click on the DscCalDi.exe.
3. Select "CCD Black" on the LCD "Test", and click the "Yes".
4. After the adjustment is completed, the number of defect will appear.
5. Click the OK.

3-9. Factory Code Setting

1. Check the "Factory Code" display within the Setting group.
2. **For U.S.A., Canada and NTSC general area**
If "FC_SANYO_U" does not appear, click on the "▼" mark located on the right of the "Factory Code" display BOX and select "FC_SANYO_U".
3. **For Europe and PAL general area**
If "FC_SANYO_EX" does not appear, click on the "▼" mark located on the right of the "Factory Code" display BOX and select "FC_SANYO_EX".

3-10. Language Setting

1. Click on the "▼" mark located on the right of the "Language" display BOX.
2. Select language. (Default is English.)
3. End "DscCal" and remove the camera before turning the camera power OFF.

The screenshot shows a camera's menu interface with several sections:

- Calibration:** Includes buttons for AWB, Focus, UV Matrix, Cal Mode (with an OK button), and Cal Data (with an OK button).
- Upload:** Includes buttons for Firmware, Data, and PAF Cal. Below these are checkboxes for EVF and VCO, and a dropdown for LCD Type.
- LCD:** Includes dropdowns for R Bright, B Bright, VCOMDC, RGB Offset, Gain, VCOMPP, Tint, Phase, H AFC, and Test. There is also a Hall Cal. button.
- USB storage:** Includes fields for VID, Serial, PID, and Rev., each with a Get or Set button. There is also a Backrush pulse field with a Get button.
- Setting:** Includes dropdowns for Language, Video Mode, and Factory Code.

3-11. Reset Setting

Carry out reset settings after replacing CP1 board.

1. Turn on the camera.
2. Set the NORMAL mode, and press the MENU button.
3. Choose the OPTION MENU 3.
4. Choose the RESET SETTINGS, and press the SET button.
5. Select RESET, and press the SET button.

3-12. The Compulsive boot starting method

1. Keep MENU button, SET button, and SHUTTER button depressed while switching on the power.
2. Connect the camera and the computer with USB cable.

3-13. Firmware uploading procedure

1. Uploading the firmware should be carried out if the version number (COMPL PWB XX-X) on the replacement circuit board is lower than the version of the distributed firmware. For XX-X, enter the name of the circuit board containing the firmware.
2. The firmware is distributed by e-mail in self-extracting archive format. Change the extension of the distributed file to .EXE and save it in your preferred folder.
3. When you double-click the saved file, the firmware (binary file) will be saved in the same folder.
4. The firmware must not be distributed without permission.

1. Overwriting firmware from the SD card

Preparation:

SD card: SD card with firmware rewritten into the root directory

Data: S314Nxxx.BIN (xxx: version)

Overwriting method:

1. Insert the above SD card.
2. Turn on the camera.
3. Set the NORMAL mode.
4. Press the MENU button.
5. Choose the OPTION MENU 3.
6. Choose the FORMAT.
7. Toggle the SET button to the left for 2 seconds. FIRMWARE UPDATE will display.
8. Choose YES.
9. Press the SET button. Update is starting.

Note:

Do not turn off the camera's power or remove the SD card while the firmware is being updated.
The power will turn off after the update is complete.

2. Overwriting firmware from the calibration software

Preparation:

PC with overwriting firmware copied to the preferred folder in the HD.

Data: S314Nxxx.BIN (xxx: version)

Overwriting method:

1. Connect the camera's USB/AV terminal to the computer's USB connector.
2. The USB Connection screen appears on the camera's LCD monitor. Choose the "COMPUTER", and press the SET button. Next, choose the "CARD READER", and press the SET button.
3. Double-click on the DscCalDi.exe.
4. Click the Firmware.
5. Choose the firmware file to use for overwriting, and click the Yes.
6. Update is starting. The message will appear, and choose OK.
7. After the update is complete, disconnect the USB cable and turn the camera's power off.

Note:

Do not turn off the camera's power while the firmware is being updated.

4. USB STORAGE INFORMATION REGISTRATION

USB storage data is important for when the camera is connected to a computer via a USB connection.

If there are any errors in the USB storage data, or if it has not been saved, the USB specification conditions will not be satisfied, so always check and save the USB storage data.

Preparation:

POWER switch: ON

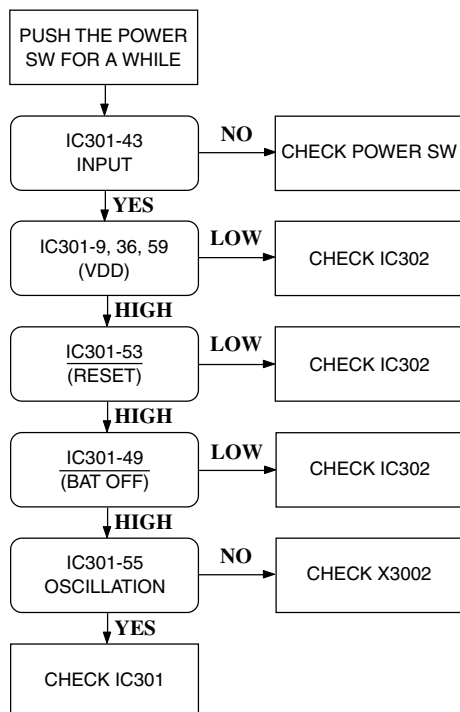
Adjustment method:

1. Connect the camera to a computer. (Refer to 3-5. Connecting the camera to the computer on the page 18.)
2. Double-click on the DscCalDi.exe.
3. Click on the Get button in the USB storage window and check the USB storage data.
VID: SANYO
PID: TH1
Serial:
Rev. : 1.00
4. Check the "Serial" in the above USB storage data. If the displayed value is different from the serial number printed on the base of the camera, enter the number on the base of the camera. Then click the Set button.
5. Next, check VID, PID and Rev. entries in the USB storage data. If any of them are different from the values in 3. above, make the changes and then click the corresponding Set button.

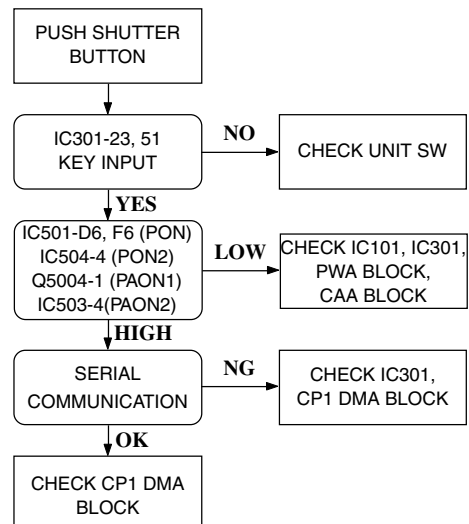
Calibration <input type="button" value="AWB"/> <input type="button" value="Focus"/> <input type="button" value="UV Matrix"/> Cal Mode <input type="text"/> <input type="button" value="OK"/> Cal Data <input type="text"/> <input type="button" value="OK"/>	Upload <input type="button" value="Firmware"/> <input type="button" value="Data"/> <input type="button" value="PAF Cal."/> <input type="checkbox"/> EVF <input type="checkbox"/> VCO LCD Type <input type="text"/>	LCD R Bright <input type="text"/> B Bright <input type="text"/> VCOMDC <input type="text"/> RGB Offset <input type="text"/> Gain <input type="text"/> VCOMPP <input type="text"/> Tint <input type="text"/> Phase <input type="text"/> H AFC <input type="text"/> Test <input type="text"/> <input type="button" value="Hall Cal."/>	
USB storage <input type="button" value="Get"/> VID <input type="text"/> <input type="button" value="Set"/> Serial <input type="text"/> <input type="button" value="Set"/> <input type="button" value="Set"/> PID <input type="text"/> <input type="button" value="Set"/> Rev. <input type="text"/> <input type="button" value="Set"/> Backrush pulse : <input type="button" value="Get"/> <input type="text"/> <input type="button" value="Set"/>			Setting Language <input type="text"/> Video Mode <input type="text"/> Factory Code <input type="text"/>

5. TROUBLESHOOTING GUIDE

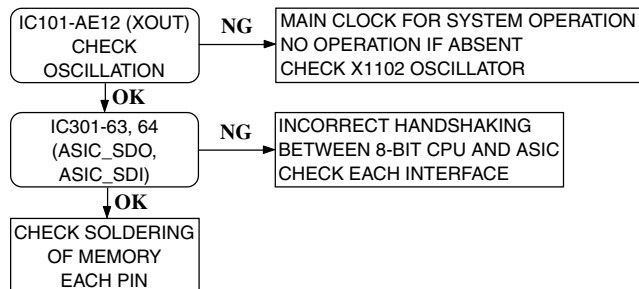
POWER LOSS INOPERATIVE



TAKING INOPERATIVE



NO PICTURE



6. PARTS LIST

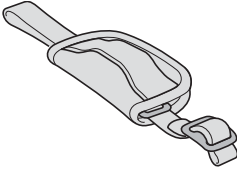
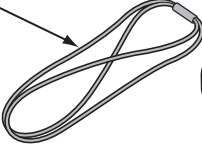
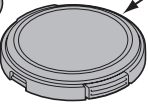
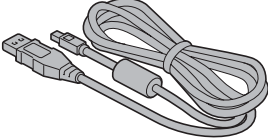
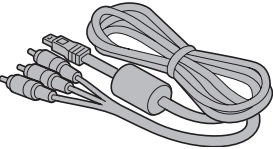
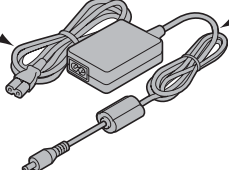
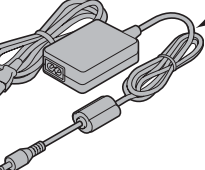
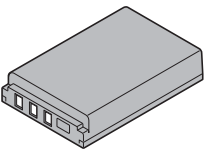
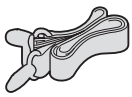



PACKING MATERIALS

LOCATION	PARTS NO.	DESCRIPTION
7001	636 122 9296	CARTON INNER-SG314/EX VPC-TH1EX,VPC-TH1GX,VPC-TH1EXR, VPC-TH1GXR,VPC-TH1EXBL,VPC-TH1GXBL
7001	636 122 9289	CARTON INNER-SG314/U VPC-TH1,VPC-TH1R,VPC-TH1BL
7001	636 126 2040	CARTON INNER-SG314/U4 VPC-ZH1R ONLY
7002	636 122 9326	REINFORCE PAD,A-SG314/J INNER BOTTOM
7003	636 077 8139	CUSHION SHEET-SX774/KRO
7004	636 123 6843	LABEL BLUE MODEL-SG314/U3 VPC-TH1BL,VPC-TH1EXBL,VPC-TH1GXBL
7004	636 123 6836	LABEL RED MODEL-SG314/U2 VPC-TH1R,VPC-TH1EXR,VPC-TH1GXR
7005	636 083 6532	LABEL CARTON BLUE-718EX2 VPC-TH1BL,VPC-TH1EXBL,VPC-TH1GXBL
7005	636 094 2158	LABEL CARTON RED-815/EX2 VPC-TH1R,VPC-TH1EXR,VPC-TH1GXR
7006	636 126 2057	CARTON INNER2-SG314/U4 VPC-ZH1R ONLY

ACCESSORIES

LOCATION	PARTS NO.	DESCRIPTION
Note: Refer to the table of accessories.		
1	636 124 1403	STRAP BELT-SG314/U
2	636 103 1783	STRAP CAP LENS-SG112/J
3	636 123 0414	ASSYL,CAP LENS-SG314
4	645 099 2780	CABLE,DSC USB (Ddicated USB inter face cable)
OR	645 099 2797	CABLE,DSC USB (Ddicated USB inter face cable)
5	645 099 2803	CABLE,DSC A/V (Ddicated AV inter face cable)
OR	645 099 2810	CABLE,DSC A/V (Ddicated AV inter face cable)
6	△ 645 098 8721	CORD,POWER-1.2MK VPC-TH1EX,VPC-TH1EXR,VPC-TH1EXBL
OR	△ 645 076 0235	CORD,POWER-1.5MK VPC-TH1EX,VPC-TH1EXR,VPC-TH1EXBL
6	△ 645 084 0104	CORD,POWER-1.8MK VPC-TH1,VPC-TH1R,VPC-TH1BL,VPC-ZH1R
OR	△ 645 098 8714	CORD,POWER-1.9MK VPC-TH1,VPC-TH1R,VPC-TH1BL,VPC-ZH1R
7	△ 645 095 6034	ADAPTOR,AC-DC
8	△ 645 098 9612	BATTERY,RECHARGE,LI-ION
9	636 126 2101	CASE SOFT-SG314/U4 VPC-ZH1R ONLY
10	645 099 2834	CABLE,DSC HDMI-TYPE A&C (Mini HDMI cable) VPC-ZH1R ONLY
11	636 127 0755	DISC,CD-ROM XSC G314 U4 (N.S.P.) Xacti software,PDF instruction manual(English, French,Spanish) VPC-ZH1R ONLY
11	636 123 2159	DISC,CD-ROM XSD G314 U (N.S.P.) Xacti software, PDF instruction manual and quick guide(English, French,German,Spanish,Italian,Dutch,Portuguese, Russian,Turkish,Korean,Traditional chinese, Simplified chinese Note:Turkish is only a quick guide.) EXCEPT VPC-ZH1R
9051	636 123 5013	INSTRUCTION MANUAL Quick guide(English, French,German,Spanish,Italian,Dutch,Portuguese, Russian) EXCEPT VPC-ZH1R
9051	636 127 3114	INSTRUCTION MANUAL Quick guide(English, French,Spanish) VPC-ZH1R ONLY
9052	636 123 5020	INSTRUCTION MANUAL Quick guide(Turkish, Korean,Traditional chinese,Simplified chinese) EXCEPT VPC-ZH1R
9053	636 123 5037	INSTRUCTION MANUAL Camera/Software (English) EXCEPT VPC-ZH1R
9053	636 127 3121	INSTRUCTION MANUAL Camera/Software (English) VPC-ZH1R ONLY

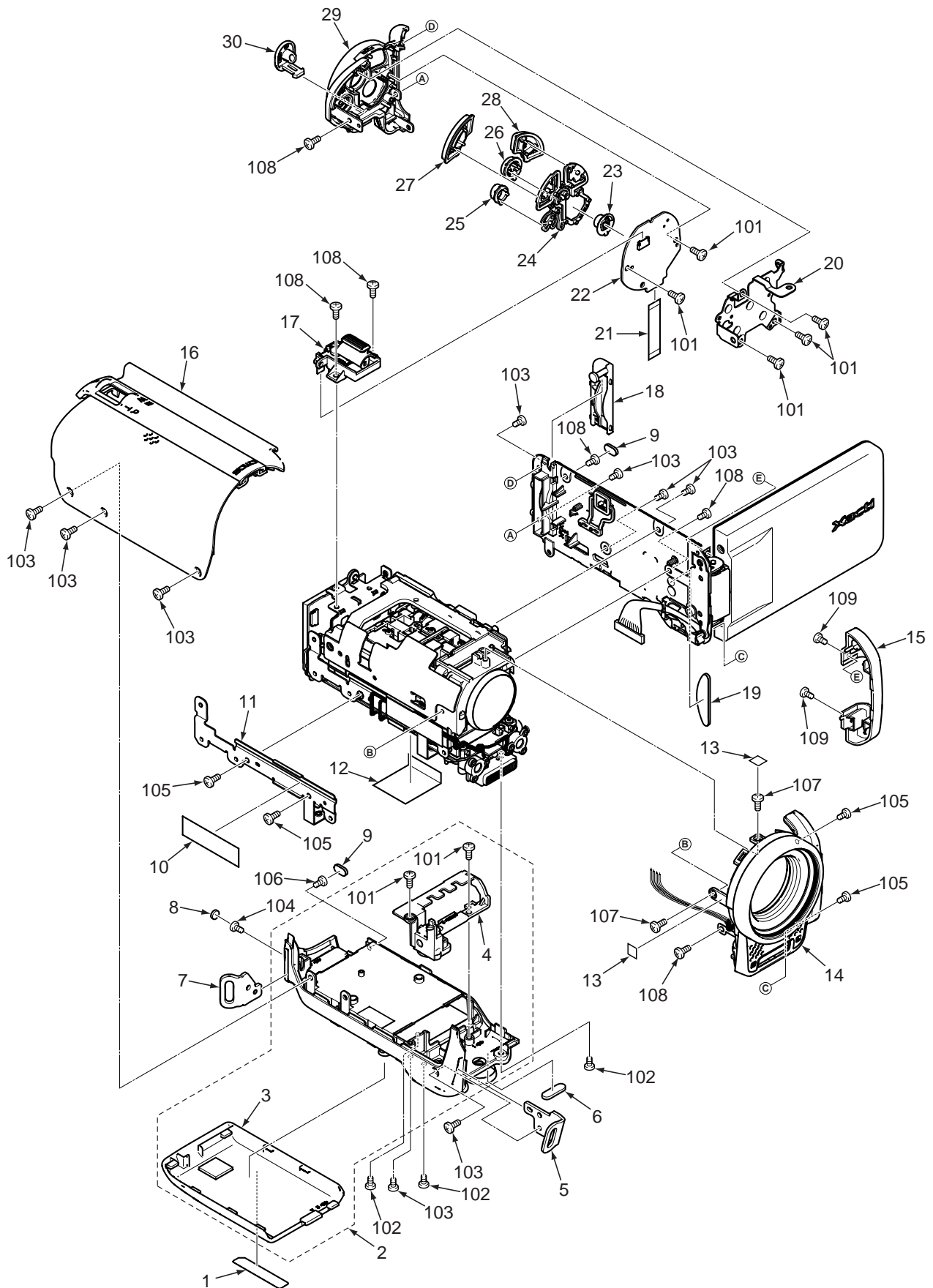
Table of accessories

<p>1</p> 	<p>2</p>  <p>3</p> 
<p>4</p> 	<p>5</p> 
<p>6</p>  <p>7</p> 	<p>8</p> 
<p>9</p>  	<p>10</p> 
<p>11</p> 	

CABINET AND CHASSIS PARTS 1

LOCATION	PARTSNO.	DESCRIPTION	LOCATION	PARTSNO.	DESCRIPTION
1	636 125 8289	LABEL CAUTION-SG217/U	20	636 121 5381	HOLDER BACK-SG314/J
2	636 122 9395	ASSY,CABI BOTTOM-SG314	21	636 122 6356	FLEXIBLE PWB CP1&TB4SG314
3	636 123 0407	ASSY,COVER BATTERY-SG314/	22	636 120 9830	COMPL PWB,TB-4
4	636 121 5442	STAND-SG314/J	23	636 121 4766	BUTTON SELECT-SG314/J
5	636 121 5350	HOLDER STRAP FRONT-SG314	24	636 121 5916	HOLDER BUTTON BAS-SG314/J
6	636 126 0633	SPACER BOTTOM-SG314/JO	25	636 121 4735	BUTTON MENU-SG314/J
7	636 121 5367	HOLDER STRAP BACK-SG314/J	26	636 121 4773	BUTTON REC PLAY-SG314/J
8	636 125 8685	SPACER BLIND-SG314/J	27	636 121 4759	BUTTON MOVIE-SG314/J
9	636 126 2439	SPACER LCD-SG314/J	28	636 121 4742	BUTTON SHUTTER-SG314/J
10	636 122 9340	SPACER MIC-SG314/J	29	636 121 4803	CABINET BACK-SG314/J
11	636 121 5428	HOLDER BOTTOM-SG314/J	30	636 121 4964	COVER DC-SG314/J
12	636 126 0671	SPACER SHILD WIRE-SG314/J	101	411 178 9403	SCR S-TPG PAN PCS 1.7X4.0
13	636 127 2582	SPACER CABI FRONT-SG314/J	102	411 193 2106	SCR S-TPG PAN PCS 1.7X4.0
14	636 123 0315	COMPL,CABINET FRONT-SG314	103	411 194 8206	SCR PAN PCS 1.7X3
15	636 121 5169	DEC JOINT-SG314/J	104	412 078 7902	SPECIAL SCREW-1.7X3.0
		VPC-TH1,VPC-TH1EX,VPC-TH1GX	105	411 178 6204	SCR PAN PCS 1.7X4
15	636 123 0520	DEC JOINT-SG314/J2 VPC-TH1R,	106	411 218 4405	SCR S-TPG PAN PCS 1.7X7
		VPC-TH1EXR,VPC-TH1GXR,VPC-ZH1R	107	411 177 9503	SCR S-TPG PAN PCS 1.7X3
15	636 123 0537	DEC JOINT-SG314/J3	108	411 175 5705	SCR PAN PCS 1.7X3
		VPC-TH1BL,VPC-TH1EXBL,VPC-TH1GXBL	109	411 184 0005	SCR PAN PCS 1.7X2.0
16	636 123 0339	COMPL,CABINET TOP-SG314			VPC-TH1,VPC-TH1EX,VPC-TH1GX
17	645 099 0168	UNIT,ZOOM-SG314/J	109	411 194 8404	SCR PAN PCS 1.7X2.0
18	636 121 4940	COVER SD-SG314/J			EXCEPT VPC-TH1,VPC-TH1EX,VPC-TH1GX
19	636 126 2446	SPACER LCD FRONT-SG314/J			

CABINET AND CHASSIS PARTS 1



CABINET AND CHASSIS PARTS 2

LOCATION	PARTS NO.	DESCRIPTION	LOCATION	PARTS NO.	DESCRIPTION
31	645 099 2308	ASSY,LAMP-SG314	57	636 121 5404	HOLDER LCD-SG314/J
32	404 120 5400	ELECT 60U A 300V	58	645 098 7229	LCD(990000412)
33	636 068 0265	COVER TRIGER-SX612/J	59	636 126 5065	ASSY,COVER LCD F-SV-SG314
34	636 126 0688	SPACER ST1-SG314/J			EXCEPT VPC-ZH1R
35	636 120 5276	COMPL PWB,ST-1	59	636 127 6085	ASSY,COVER LCD F-SV-SG314 VPC-ZH1R ONLY
36	636 121 5251	SPACER CON ST1-SG314/J	60	636 121 5138	HEAT SINK CMOS-SG314/J
37	636 123 3057	COMPL PWB,CP-1 F/W	61	636 121 5213	HOLDER LENS CHASSIS-SG314
38	636 121 5329	HEAT SINK RUB ASIC-SG314	62	636 105 2207	HOLDER LENS-SG211/J
39	636 121 5183	CHASSIS BOTTOM-SG314/J	63	636 127 1820	SPACER LENS BOTTOM-SG314
40	636 120 9823	COMPL PWB,TB-3	64	645 099 3169	LENS(ASSY)
41	636 121 5176	CHASSIS RIGHT-SG314/J	65	645 099 2520	OPTICAL FILTER
42	636 121 5107	EARTH JACK-SG314/J	66	636 122 4772	SPACER SG314
43	636 122 6349	FLEXIBLE PWB CP1&TB3SG314	67	636 122 8558	ASSY,FPC CA1 SV-SG314
44	636 121 4926	COVER JOINT-SG314/J	68	636 127 4050	HEAT SINK TAPE CMOS-SG314
		VPC-TH1,VPC-TH1EX,VPC-TH1GX	69	636 125 7206	HOLDER HEAT CMOS TB1-314
44	636 123 0483	COVER JOINT-SG314/J2 VPC-TH1R,	70	636 121 5374	HOLDER TB1-SG314/J
		VPC-TH1EXR,VPC-TH1GXR,VPC-ZH1R	71	636 121 5282	SPACER CA-SG314/J
44	636 123 0490	COVER JOINT-SG314/J3 VPC-TH1BL,	72	636 121 5312	HOLDER CA-SG314/J
		VPC-TH1EXBL,VPC-TH1GXBL	73	636 120 9816	COMPL PWB,TB-1
45	636 121 5336	ASSY,JOINT-SG314/J	101	411 178 9403	SCR S-TPG PAN PCS 1.7X4.0
46	636 106 6310	ASSY,SHIELD WIRE CP1-VF1	105	411 178 6204	SCR PAN PCS 1.7X4
47	636 120 5054	COMPL PWB,TB-2	106	411 218 4405	SCR S-TPG PAN PCS 1.7X7
48	636 121 4780	BUTTON POWER-SG314/J	107	411 177 9503	SCR S-TPG PAN PCS 1.7X3
49	636 121 5268	HOLDER WIRE-SG314/J	108	411 175 5705	SCR PAN PCS 1.7X3
50	636 127 3152	SPACER HOLDER JOINT-SG314	110	411 176 1003	SCR PAN PCS 1.7X2.5
51	636 121 5411	HOLDER JOINT-SG314/J	111	411 181 2705	SCR PAN PCS-1.4X2
52	636 121 4865	CABINET RIGHT-SG314/J	112	411 199 0601	SCR TIN 1.7X2
53	636 126 5089	ASSY,COVER LCD B-SV-314			EXCEPT VPC-TH1,VPC-TH1EX,VPC-TH1GX
		VPC-TH1,VPC-TH1EX,VPC-TH1GX	112	411 199 0700	SCR TIN 1.7X2
53	636 126 5119	ASSY,COVER LCD B-SV-314 VPC-TH1R,			VPC-TH1,VPC-TH1EX,VPC-TH1GX
		VPC-TH1EXR,VPC-TH1GXR,VPC-ZH1R	113	411 184 0005	SCR PAN PCS 1.7X2.0
53	636 126 5133	ASSY,COVER LCD B-SV-314	114	411 175 5705	SCR PAN PCS 1.7X3
		VPC-TH1BL,VPC-TH1EXBL,VPC-TH1GXBL			VPC-TH1,VPC-TH1EX,VPC-TH1GX
54	636 127 1608	SPACER LCD FPC-SG314/J	114	411 194 8206	SCR PAN PCS 1.7X3
55	636 120 9809	COMPL PWB,VF-1			EXCEPT VPC-TH1,VPC-TH1EX,VPC-TH1GX
56	636 121 5237	SPACER PWB-SG314/J	115	411 178 0103	SCR S-TPG PAN PCS 1.4X3.5

[illegible]

Note:

Resistors

MT-FILM

MT-GLAZE

OXIDE-MT

Metallized Film Resistor

Metallized Glaze Resistor

Oxide Metallized Film Resistor

Capacitors

MT-POLYEST

MT-COMPO

TA-SOLID

AL-SOLID

NP-ELECT

OS-SOLID

DL-ELECT

POS-SOLID

Metallized Polyester Capacitor

Metallized Composite Capacitor

Tantalum Solid Capacitor

Aluminum Solid Capacitor

Non-Polarized Electrolytic Capacitor

Aluminum Solid Capacitors with Organic

Semiconductive Electrolytic Capacitor

Double Layered Electrolytic Capacitor

Polymerized Organic Semiconductor Capacitor

F1% G2% J5% K10%

M20% N30% Z+80% ~ -20%

3. Capacitors

U : μ F P : pF

4. Inductors

UH : μH

MH : mH

5. N.S.P. : Not available as service parts.

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LOCATION	PARTS NO.	DESCRIPTION	LOCATION	PARTS NO.	DESCRIPTION
C1001	303 311 3501	CERAMIC 1000P K 50V	C5055	303 334 0907	CERAMIC 1U K 6.3V
C1005	303 382 2700	CERAMIC 4.7U K 6.3V	C5061	303 382 2700	CERAMIC 4.7U K 6.3V
C1006	303 343 4705	CERAMIC 0.1U K 10V	C5062	303 358 3205	CERAMIC 10U K 6.3V
C1010	303 343 4705	CERAMIC 0.1U K 10V	C5071	403 455 1408	CERAMIC 2.2U K 16V
C1012	303 343 4705	CERAMIC 0.1U K 10V	C5072	303 383 5007	CERAMIC 1U K 16V
C1013	303 343 4705	CERAMIC 0.1U K 10V	C5073	303 311 3303	CERAMIC 0.01U K 16V
C1017	303 391 3804	CERAMIC 1U K 6.3V	C5074	303 334 0907	CERAMIC 1U K 6.3V
C1018	303 311 3303	CERAMIC 0.01U K 16V	C5111	303 382 2700	CERAMIC 4.7U K 6.3V
C1047	303 382 2700	CERAMIC 4.7U K 6.3V	C5112	303 358 3205	CERAMIC 10U K 6.3V
C1048	303 382 2700	CERAMIC 4.7U K 6.3V	C5201	403 455 1408	CERAMIC 2.2U K 16V
C1051	303 343 4705	CERAMIC 0.1U K 10V	C5202	403 455 1408	CERAMIC 2.2U K 16V
C1052	303 343 4705	CERAMIC 0.1U K 10V	C5204	303 348 1204	CERAMIC 0.068U K 10V
C1053	303 343 4705	CERAMIC 0.1U K 10V	C5206	403 455 1002	CERAMIC 1U K 10V
C1054	303 343 4705	CERAMIC 0.1U K 10V	C5207	403 455 1002	CERAMIC 1U K 10V
C1057	303 343 4705	CERAMIC 0.1U K 10V	C5208	403 455 1002	CERAMIC 1U K 10V
C1058	303 343 4705	CERAMIC 0.1U K 10V	C5301	303 358 3205	CERAMIC 10U K 6.3V
C1063	303 343 4705	CERAMIC 0.1U K 10V	C5302	303 381 1209	POS-SOLID 33U M 6.3V
C1064	303 343 4705	CERAMIC 0.1U K 10V	C5303	303 309 8709	CERAMIC 100P J 50V
C1065	303 343 4705	CERAMIC 0.1U K 10V	C5304	303 383 5007	CERAMIC 1U K 16V
C1066	303 343 4705	CERAMIC 0.1U K 10V	C9001	303 391 3804	CERAMIC 1U K 6.3V
C1121	303 314 6509	CERAMIC 7P D 50V	C9002	303 374 5801	CERAMIC 0.22U K 6.3V
C1122	303 314 6509	CERAMIC 7P D 50V	C9003	303 382 2700	CERAMIC 4.7U K 6.3V
C1201	303 384 9202	CERAMIC 1U M 4V	C9004	303 391 3804	CERAMIC 1U K 6.3V
C1204	303 343 4705	CERAMIC 0.1U K 10V	C9006	303 419 8903	CERAMIC 10U M 6.3V
C1205	303 343 4705	CERAMIC 0.1U K 10V	C9009	303 374 5801	CERAMIC 0.22U K 6.3V
C1206	303 343 4705	CERAMIC 0.1U K 10V	C9011	303 391 3804	CERAMIC 1U K 6.3V
C1207	303 343 4705	CERAMIC 0.1U K 10V	C9013	303 334 0907	CERAMIC 1U K 6.3V
C1208	303 343 4705	CERAMIC 0.1U K 10V	C9502	303 343 4705	CERAMIC 0.1U K 10V
C1209	303 375 0300	CERAMIC 4.7U K 4V	C9504	303 343 4705	CERAMIC 0.1U K 10V
C1304	403 455 1002	CERAMIC 1U K 10V	C9505	303 343 4705	CERAMIC 0.1U K 10V
C1506	303 391 3804	CERAMIC 1U K 6.3V	C9506	303 343 4705	CERAMIC 0.1U K 10V
C1507	303 391 3804	CERAMIC 1U K 6.3V	C9508	303 340 2803	CERAMIC 2.2U K 10V
C1509	303 391 3804	CERAMIC 1U K 6.3V	C9510	303 311 3501	CERAMIC 1000P K 50V
C1510	303 419 8903	CERAMIC 10U M 6.3V	C9511	303 313 3905	CERAMIC 680P K 50V
C1511	303 382 2700	CERAMIC 4.7U K 6.3V	C9512	303 313 3905	CERAMIC 680P K 50V
C1512	303 439 8402	CERAMIC 2.2U K 6.3V	C9513	303 343 4705	CERAMIC 0.1U K 10V
C1513	303 382 2700	CERAMIC 4.7U K 6.3V	C9515	303 343 4705	CERAMIC 0.1U K 10V
C1514	303 382 2700	CERAMIC 4.7U K 6.3V	C9516	303 358 8309	CERAMIC 1U K 10V
C1515	303 382 2700	CERAMIC 4.7U K 6.3V	C9517	303 311 3501	CERAMIC 1000P K 50V
C1801	303 343 4705	CERAMIC 0.1U K 10V	C9518	303 343 4705	CERAMIC 0.1U K 10V
C1802	303 382 2700	CERAMIC 4.7U K 6.3V	C9519	303 313 3905	CERAMIC 680P K 50V
C1804	303 343 4705	CERAMIC 0.1U K 10V	C9520	303 311 3501	CERAMIC 1000P K 50V
C1805	303 343 4705	CERAMIC 0.1U K 10V	C9523	303 374 5801	CERAMIC 0.22U K 6.3V
C1810	303 439 8402	CERAMIC 2.2U K 6.3V	C9524	303 358 8309	CERAMIC 1U K 10V
C1811	303 311 7301	CERAMIC 4700P K 25V	(RESISTOR PACKS)		
C1812	303 382 2700	CERAMIC 4.7U K 6.3V	RB101	645 040 1756	R-NETWORK 10KX4 1/32W
C1818	303 343 4705	CERAMIC 0.1U K 10V	RB102	645 078 4019	R-NETWORK 0X2 0.063W
C1901	303 391 3804	CERAMIC 1U K 6.3V	RB103	645 072 9119	R-NETWORK 150X4 1/16W
C1902	303 391 3804	CERAMIC 1U K 6.3V	RB104	645 072 9119	R-NETWORK 150X4 1/16W
C1903	303 391 3804	CERAMIC 1U K 6.3V	RB106	645 066 4328	R-NETWORK 47X4 1/16W
C1904	303 311 5109	CERAMIC 3P C 50V	RB107	645 066 4328	R-NETWORK 47X4 1/16W
C1905	303 311 5109	CERAMIC 3P C 50V	RB109	645 066 4328	R-NETWORK 47X4 1/16W
C1906	303 343 4705	CERAMIC 0.1U K 10V	RB110	645 066 4328	R-NETWORK 47X4 1/16W
C1907	303 391 3804	CERAMIC 1U K 6.3V	RB111	645 040 1756	R-NETWORK 10KX4 1/32W
C1908	303 343 4705	CERAMIC 0.1U K 10V	RB181	645 091 2900	R-NETWORK 20KX2 1/16W
C1909	303 391 3804	CERAMIC 1U K 6.3V	RB182	645 078 4613	R-NETWORK 2.2KX2 0.063W
C1910	303 311 3303	CERAMIC 0.01U K 16V	RB183	645 091 2887	R-NETWORK 200X2 1/16W
C1911	303 343 4705	CERAMIC 0.1U K 10V	RB184	645 078 4002	R-NETWORK 100KX2 0.063W
C3001	303 391 0506	CERAMIC 10U K 6.3V	RB303	645 029 6000	R-NETWORK 100KX4 1/32W
C3005	303 391 3804	CERAMIC 1U K 6.3V	RB304	645 032 8862	R-NETWORK 47KX4 1/32W
C3006	303 391 3804	CERAMIC 1U K 6.3V	RB305	645 029 5997	R-NETWORK 1KX4 1/32W
C3012	303 311 7103	CERAMIC 22P J 50V	RB306	645 051 0854	R-NETWORK 330X4 1/32W
C3015	303 311 7103	CERAMIC 22P J 50V	RB307	645 029 5997	R-NETWORK 1KX4 1/32W
C5001	303 343 4705	CERAMIC 0.1U K 10V	RB311	645 072 9157	R-NETWORK 150KX2 0.063W
C5003	303 373 5307	CERAMIC 4.7U K 6.3V	RB312	645 078 4002	R-NETWORK 100KX2 0.063W
C5004	303 319 3008	CERAMIC 220P J 25V	RB951	645 078 4606	R-NETWORK 220X2 0.063W
C5005	403 455 1002	CERAMIC 1U K 10V	RB952	645 064 1619	R-NETWORK 39KX2 1/16W
C5006	303 346 2302	CERAMIC 0.1U K 10V	(RESISTORS)		
C5007	303 383 5007	CERAMIC 1U K 16V	R1001	301 224 9009	MT-GLAZE 10K JA 1/16W
C5021	303 392 5005	CERAMIC 22U M 6.3V	R1002	301 237 2905	MT-GLAZE 51 JA 1/16W
C5022	303 392 5005	CERAMIC 22U M 6.3V	R1008	301 224 9009	MT-GLAZE 10K JA 1/16W
C5024	303 311 7103	CERAMIC 22P J 50V	R1010	301 224 9306	MT-GLAZE 1K JA 1/16W
C5031	303 392 5005	CERAMIC 22U M 6.3V	R1014	301 224 8804	MT-GLAZE 100 JA 1/16W
C5032	303 311 4805	CERAMIC 470P K 50V	R1015	301 225 1200	MT-GLAZE 4.7K JA 1/16W
C5033	303 378 5302	CERAMIC 1U K 10V	R1019	301 226 1506	MT-GLAZE 0.000 ZA 1/16W
C5036	303 334 0907	CERAMIC 1U K 6.3V	R1020	301 224 8804	MT-GLAZE 100 JA 1/16W
C5037	303 334 0907	CERAMIC 1U K 6.3V	R1021	301 224 9009	MT-GLAZE 10K JA 1/16W

LOCATION	PARTS NO.	DESCRIPTION
(MISCELLANEOUS)		
	636 121 5244	HOLDER TERMINAL BAT-SG314
	411 178 9403	SCR S-TPG PAN PCS 1.7X4.0
	636 121 5534	TERMINAL BATT-SG314/J
COMPL PWB,TB-1		
636 120 9816		
(SEMICONDUCTORS)		
Q1403	305 167 0406	TR EMD12
OR	405 218 3902	TR UP0431300
OR	305 216 2108	TR RN4984FE
(RECHARGEABLE BATTERY)		
Z6301	945 051 6000	BATTERY, RECHARGE
(CAPACITORS)		
C1401	303 311 7301	CERAMIC 4700P K 25V
C1402	303 309 8402	CERAMIC 10P D 50V
C1403	303 309 8402	CERAMIC 10P D 50V
C1404	303 309 8402	CERAMIC 10P D 50V
C1405	303 309 8402	CERAMIC 10P D 50V
C1406	303 309 8402	CERAMIC 10P D 50V
C1408	303 311 7301	CERAMIC 4700P K 25V
C1409	303 311 7301	CERAMIC 4700P K 25V
C1410	303 311 5109	CERAMIC 3P C 50V
(RESISTOR PACKS)		
RB141	645 029 5980	R-NETWORK 100X4 1/32W
RB142	645 040 1756	R-NETWORK 10KX4 1/32W
RB143	645 040 1756	R-NETWORK 10KX4 1/32W
(RESISTORS)		
R1401	301 224 8804	MT-GLAZE 100 JA 1/16W
R1402	301 225 8100	MT-GLAZE 10 JA 1/16W
(CONNECTORS)		
CN141	645 092 8185	SOCKET,CARD(SD)12(N.S.P.)
CN142	945 075 2231	SOCKET,PWB-PWB 20(N.S.P.)
COMPL PWB,TB-2		
636 120 5054		
(SWITCH)		
S6501	645 092 3159	SWITCH,PUSH 1P-1TX1
(MISCELLANEOUS)		
	636 122 6318	ASSY,WIRE VF1&TB2-SG314 (N.S.P.)
	636 122 6325	ASSY,WIRE VF1&TB2-SG314 (N.S.P.)
COMPL PWB,TB-3		
636 120 9823		
(INTEGRATED CIRCUIT)		
IC611	409 690 2309	IC MRX1518HTA
(CAPACITOR)		
C6101	303 343 4705	CERAMIC 0.1U K 10V
(SWITCH)		
S6110	645 057 0773	SWITCH,PUSH 1P-1T
(CONNECTOR)		
CN611	645 073 7060	SOCKET,FPC 6P (N.S.P.)
COMPL PWB,TB-4		
636 120 9830		
(SWITCHES)		
S6201	645 054 8857	SWITCH,PUSH 1P-2TX1
S6202	645 079 1499	SWITCH,PUSH(4DIR+CENTER)
S6203	645 098 9094	SWITCH,PUSH 1P-1T
S6204	645 057 0773	SWITCH,PUSH 1P-1T
S6205	645 057 0773	SWITCH,PUSH 1P-1T
(CONNECTORS)		
CN621	645 097 6155	SOCKET,FPC 17P (N.S.P.)
CN622	645 073 7060	SOCKET,FPC 6P (N.S.P.)

LOCATION	PARTS NO.	DESCRIPTION
COMPL PWB,VF-1		
636 120 9809		
(CAPACITORS)		
C1701	303 391 3804	CERAMIC 1U K 6.3V
C1702	403 455 1002	CERAMIC 1U K 10V
C1703	303 396 9504	CERAMIC 2.2U K 10V
C1704	303 396 9504	CERAMIC 2.2U K 10V
C1705	303 396 9504	CERAMIC 2.2U K 10V
C1706	303 396 9504	CERAMIC 2.2U K 10V
C1707	303 281 2405	CERAMIC 0.22U K 16V
C1708	303 281 2405	CERAMIC 0.22U K 16V
C1709	303 383 5007	CERAMIC 1U K 16V
C1710	303 383 5007	CERAMIC 1U K 16V
C1712	303 391 3804	CERAMIC 1U K 6.3V
(RESISTOR PACKS)		
RB171	645 072 9119	R-NETWORK 150X4 1/16W
RB172	645 072 9119	R-NETWORK 150X4 1/16W
(RESISTORS)		
R1701	301 226 1506	MT-GLAZE 0.000 ZA 1/16W
R1702	301 228 4505	MT-GLAZE 2.2 JA 1/16W
R1703	301 224 8903	MT-GLAZE 100K JA 1/16W
(CONNECTORS)		
CN171	645 093 9228	SOCKET,FPC 39P (N.S.P.)
CN172	645 093 7033	SOCKET,PWB-WIRE 3(N.S.P.)
COMPL PWB,ST-1		
636 120 5276		
(SEMICONDUCTOR)		
Q5402	406 021 5107	TR TIG032TS-S-TL-E
(INTEGRATED CIRCUIT)		
IC541	409 684 3800	IC BD4218NUV
(DIODES)		
D5401	307 245 6805	DIODE FPSN4
D5402	407 265 1900	DIODE RE0208DA-TR-E
D5404	307 221 4108	DIODE MA2SD19
(TRANSFORMERS)		
T5401	645 097 3864	TRANS,STEP UP
T5402	645 084 1835	TRANS,STEP UP
(CAPACITORS)		
C5401	303 392 5005	CERAMIC 22U M 6.3V
C5410	303 428 3302	CERAMIC 0.022U K 350V
C5411	303 428 3609	CERAMIC 0.01U K 350V
C5431	303 391 3804	CERAMIC 1U K 6.3V
C5432	303 391 3804	CERAMIC 1U K 6.3V
C5433	303 311 3501	CERAMIC 1000P K 50V
C5434	303 311 3501	CERAMIC 1000P K 50V
C5435	303 311 5000	CERAMIC 33P J 50V
(RESISTOR PACK)		
RB541	645 029 5997	R-NETWORK 1KX4 1/32W
(RESISTORS)		
R5402	302 106 1609	MT-GLAZE 100K JD 1/8W
R5422	302 106 1708	MT-GLAZE 220K JD 1/8W
R5424	301 224 9009	MT-GLAZE 10K JA 1/16W
R5425	301 225 1804	MT-GLAZE 47 JA 1/16W
R5431	301 224 8804	MT-GLAZE 100 JA 1/16W
R5432	301 224 9009	MT-GLAZE 10K JA 1/16W
R5433	301 225 0609	MT-GLAZE 5.6K JA 1/16W
R5434	301 225 0203	MT-GLAZE 3.3K JA 1/16W
R5435	301 224 8804	MT-GLAZE 100 JA 1/16W
(CONNECTOR)		
CN541	645 092 3906	SOCKET,PWB-PWB 20 (N.S.P.)

CIRCUIT DIAGRAMS & PRINTED WIRING BOARDS

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TB1 P.W.B. (SIDE A & B)	C24
TB2 P.W.B. (SIDE A & B)	C24
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ST1 P.W.B. (SIDE A & B)	C25
TB4 P.W.B. (SIDE A & B)	C26

NOTES:

1. All resistance values in "OHMS" unless otherwise noted.
(K=1,000 ; M=1,000,000)
2. All capacitance values in " μ F" unless otherwise noted.
p=pico farad ; n=nano farad ; μ ,u or U=micro farad
3. All inductance values in " μ H" unless otherwise noted.
 μ ,u or U=micro henry ; m=milli henry

Figure of printed wiring boards

Multilayer board:


"Side A" means the view from A side of the board.

"Side B" means the view from B side of the board.

Singlelayer board:

View from the copper-foil side of the board, otherwise noted.

PRODUCT SAFETY NOTICE

THE COMPONENTS DESIGNATED BY A SYMBOL () IN THIS SCHEMATIC DIAGRAM DESIGNATES COMPONENTS WHOSE VALUE ARE OF SPECIAL SIGNIFICANCE TO PRODUCT SAFETY. SHOULD ANY COMPONENT DESIGNATED BY A SYMBOL NEED TO BE REPLACED, USE ONLY THE PART DESIGNATED IN THE PARTS LIST. DO NOT DEVIATE FROM THE RESISTANCE, WATTAGE AND VOLTAGE RATINGS SHOWN.

EXPLANATORY NOTES (EXAMPLES)

Resistor 10K:1/16J means 10kilo ohm $\pm 5\%$, 1/16watt max.
1M:1/10D means 1mega ohm $\pm 0.5\%$, 1/10watt max.
(Tolerance K: $\pm 10\%$, J: $\pm 5\%$, G: $\pm 2\%$, F: $\pm 1\%$, D: $\pm 0.5\%$)

Capacitor 0.047:F means 0.047micro farad, Ftype.

Electrolytic capacitor
10:16 means 10micro farad, 16volt max.

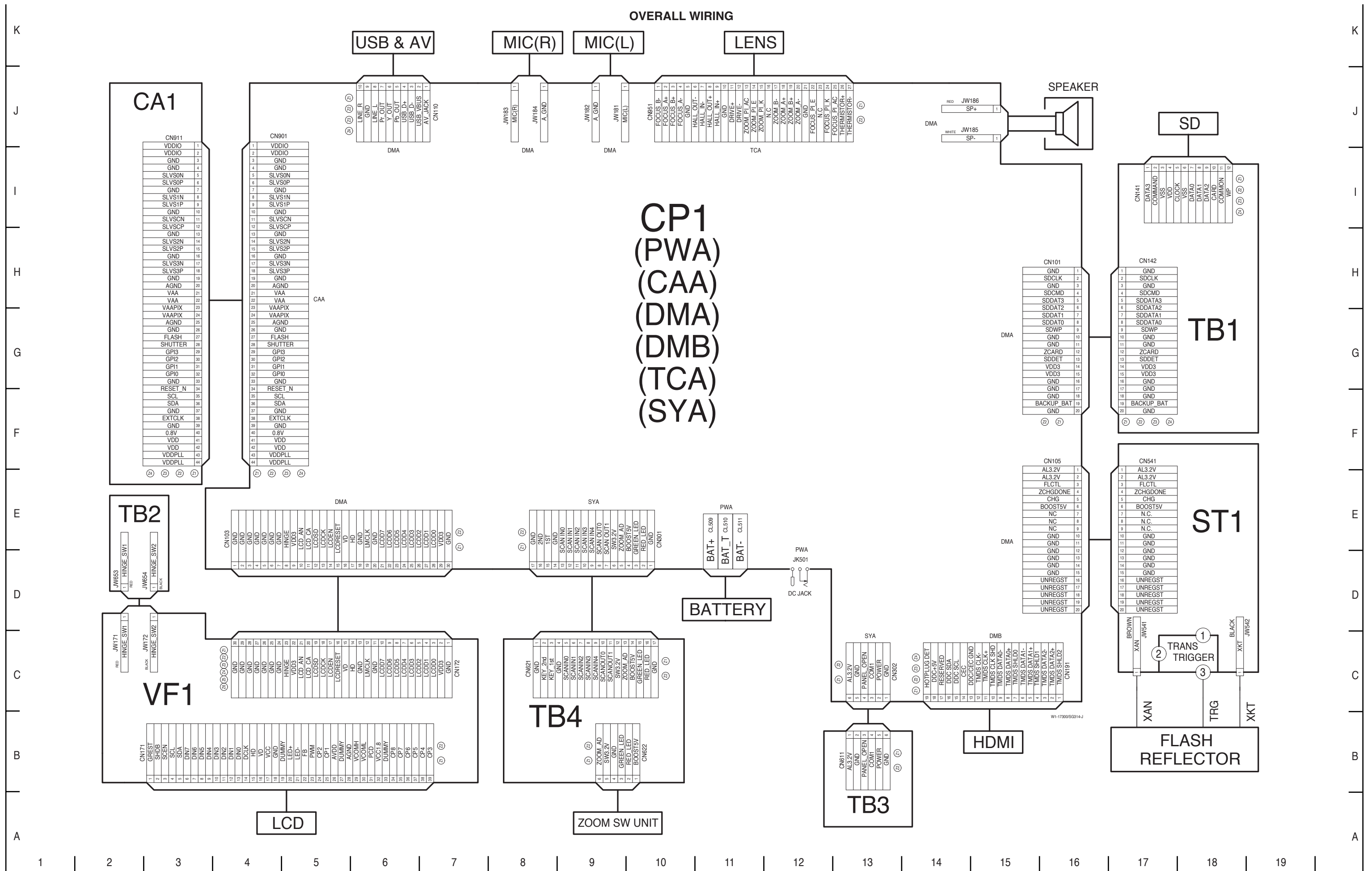
Inductor 330:J means 330micro henry $\pm 5\%$
470:K means 470micro henry $\pm 10\%$
No description J or K means $\pm 5\%$

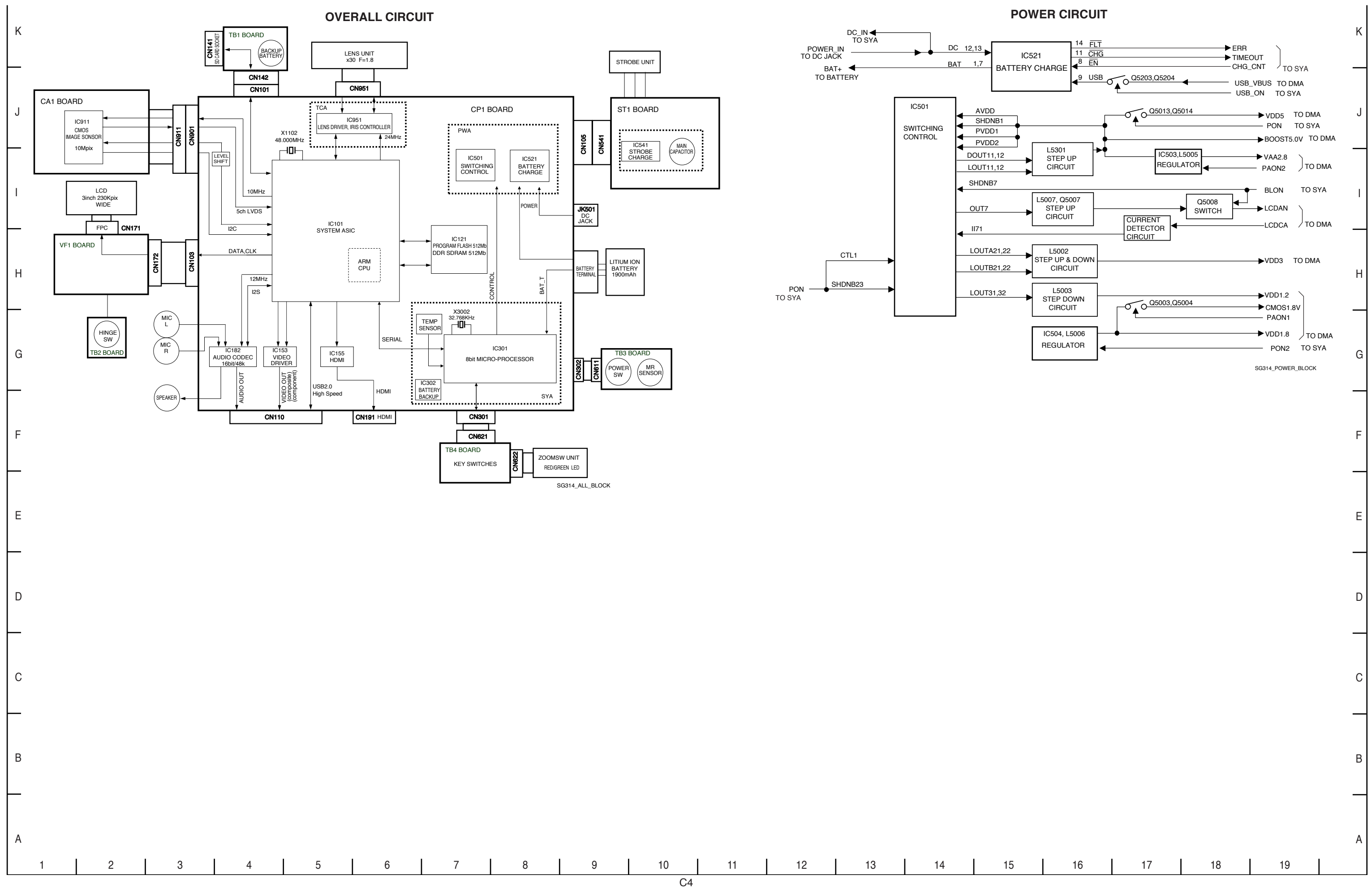
The number of "H=##" written in slant character, shows the voltage.

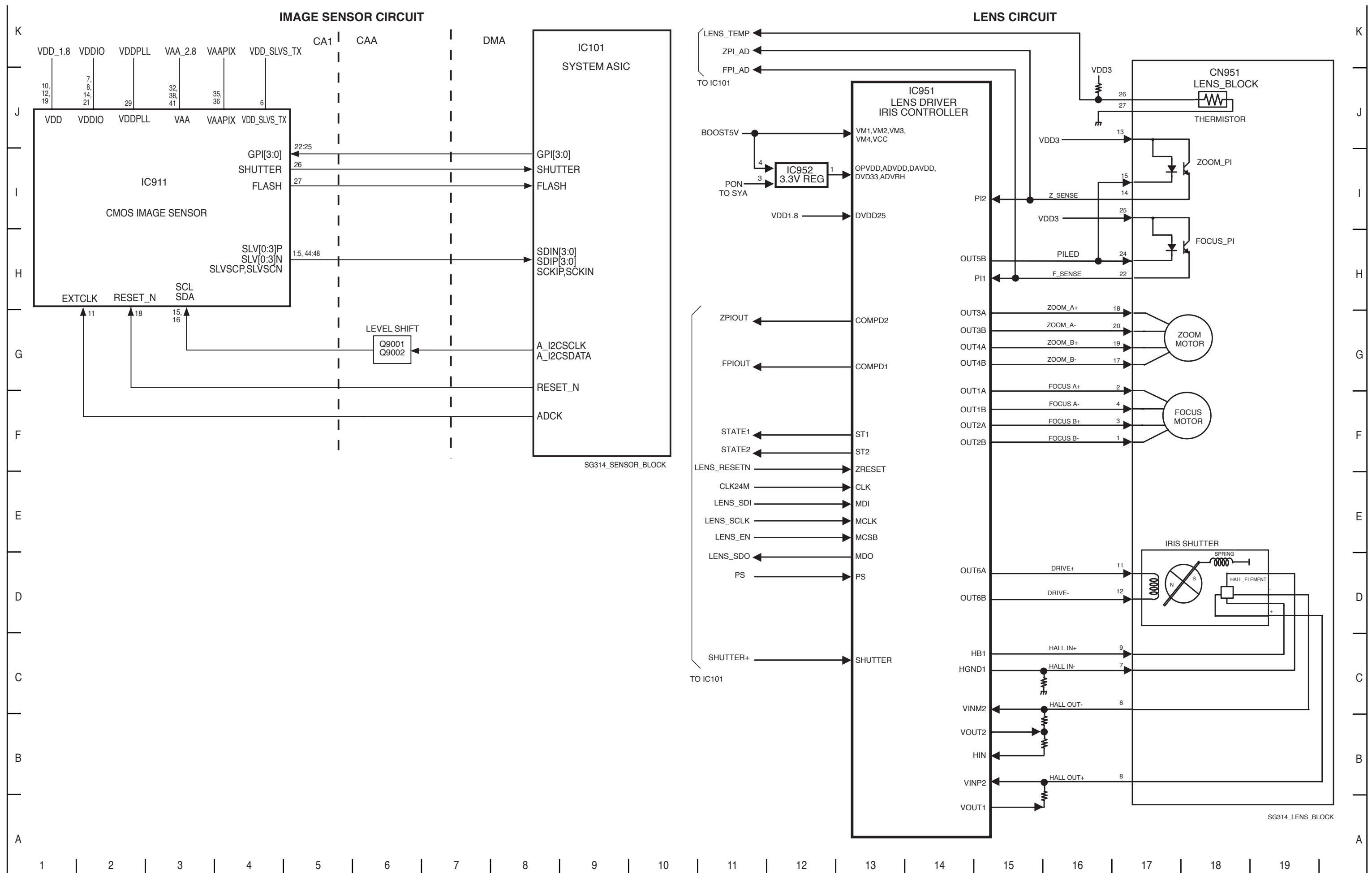
The number of "H=##" written in upright character, shows the height of the parts.

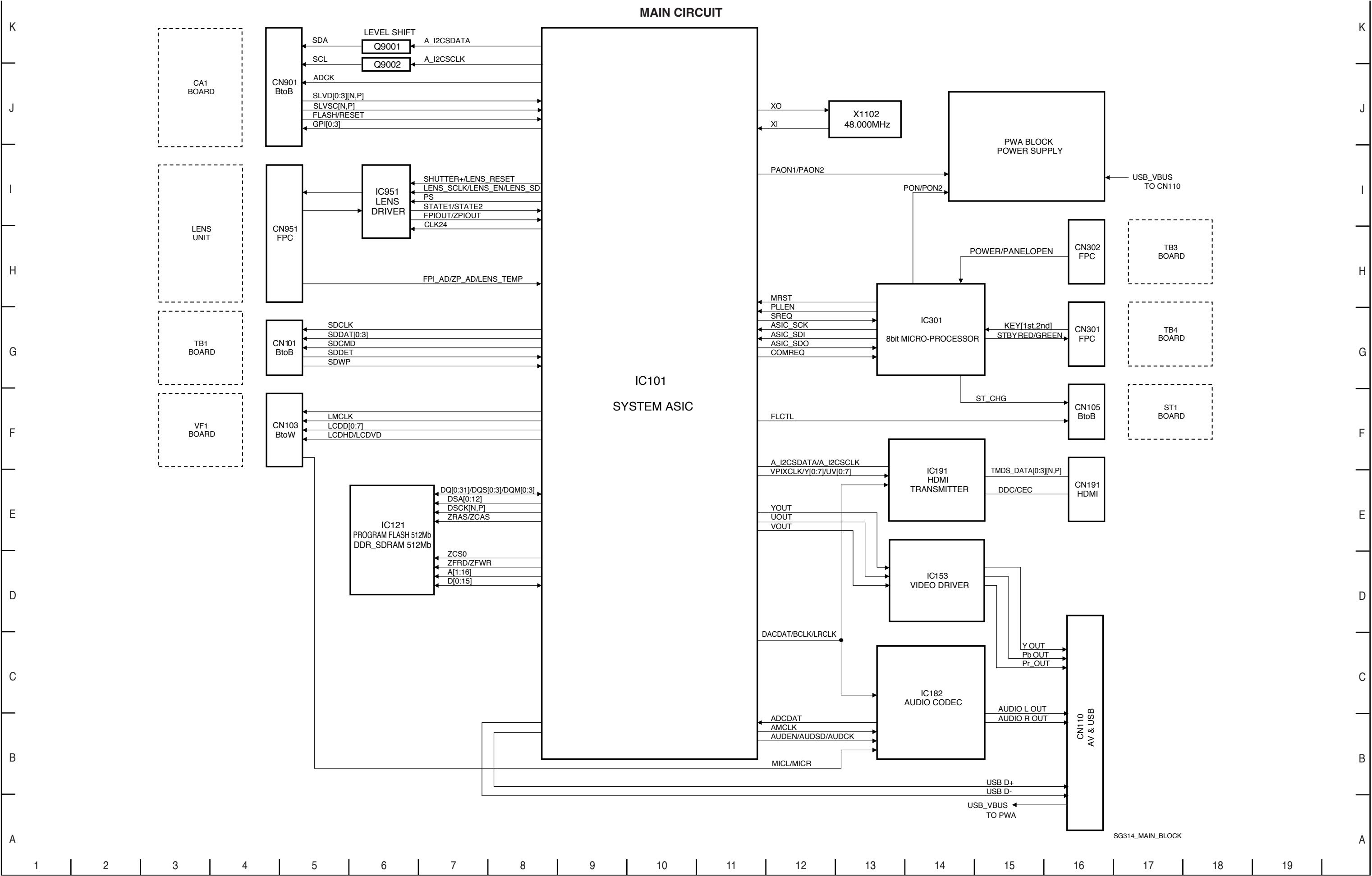
PAL-H-EX

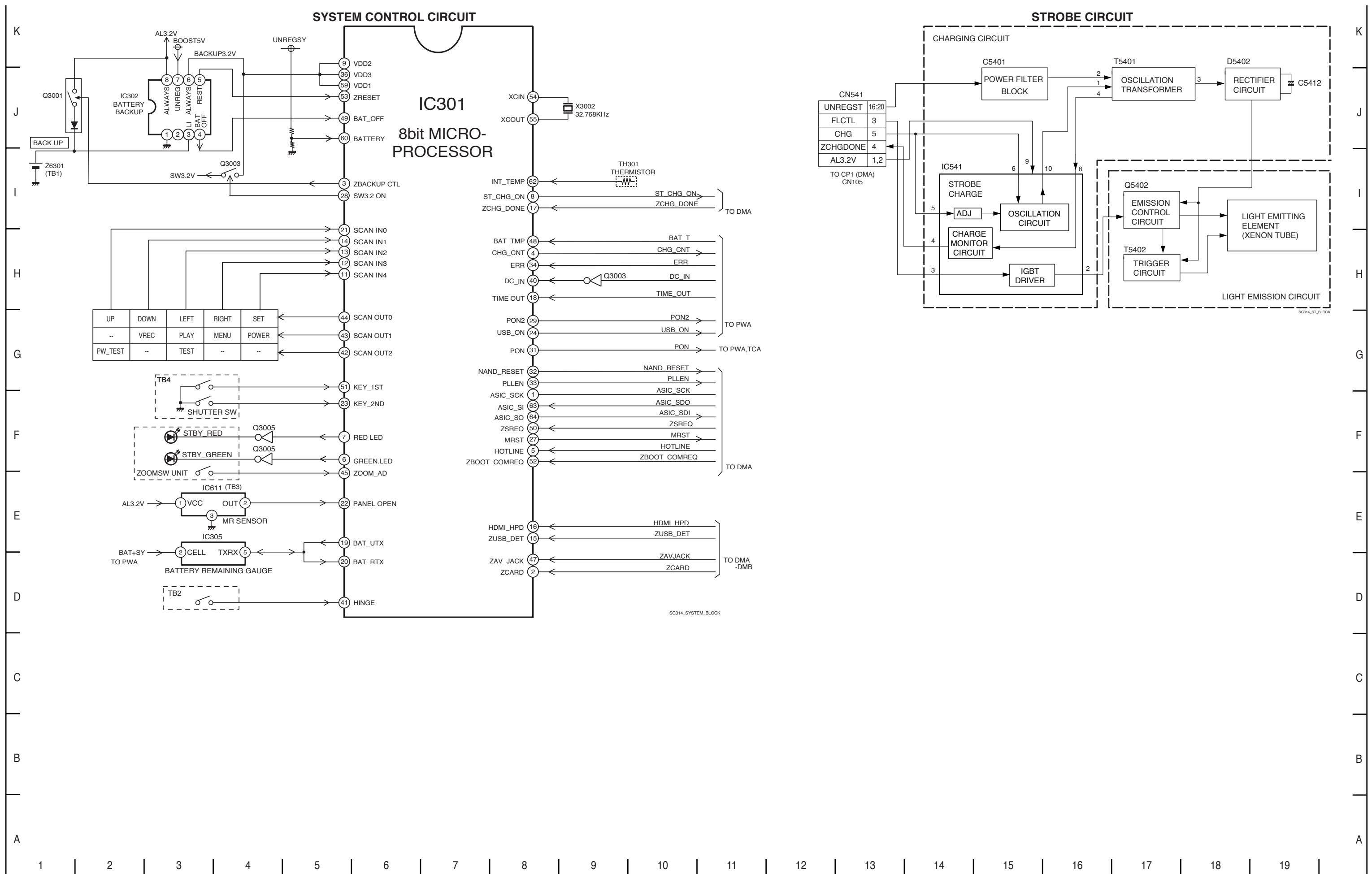
OVERALL WIRING & BLOCK DIAGRAMS





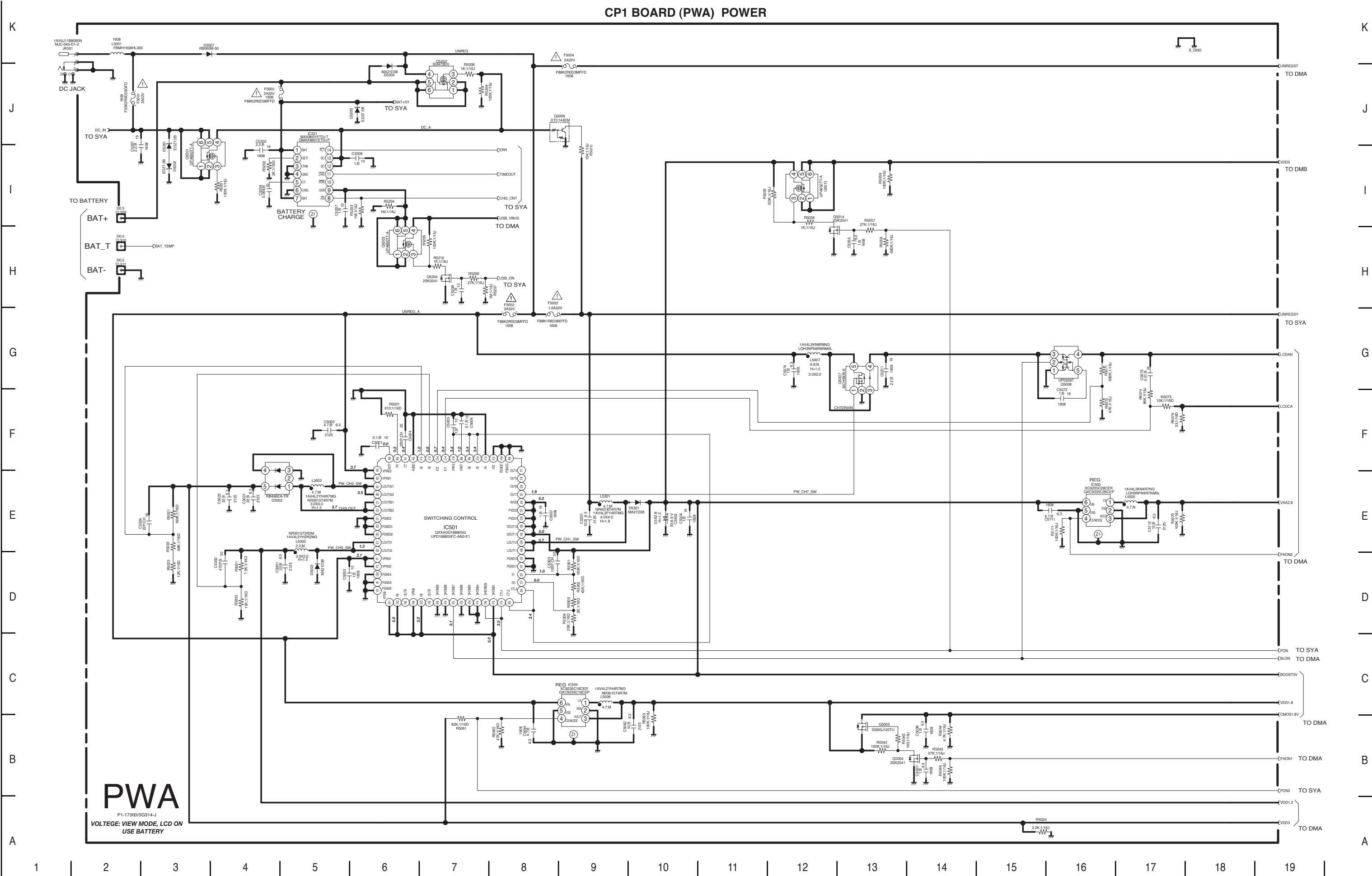






CIRCUIT DIAGRAMS

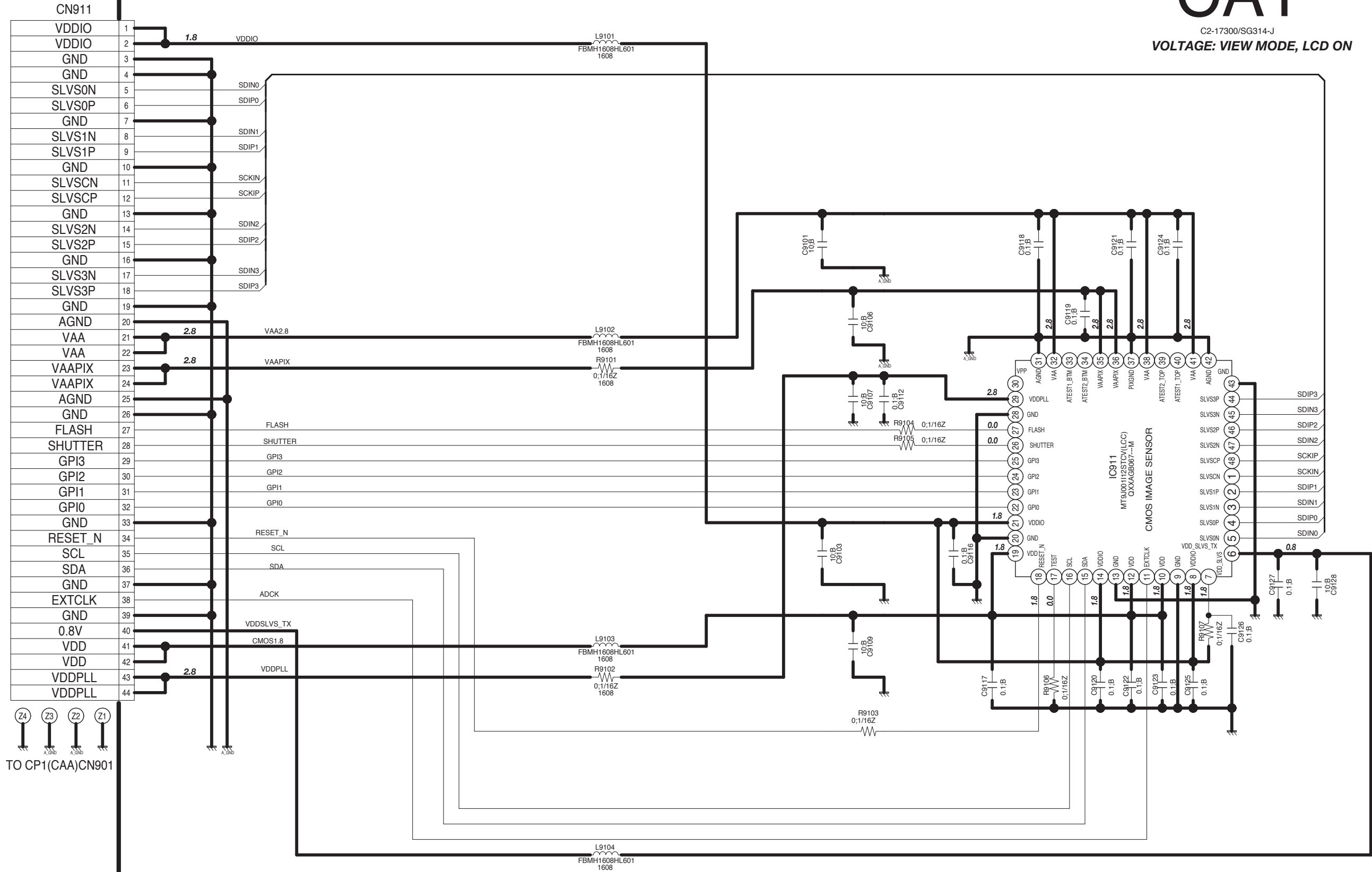
CP1 BOARD (PWA) POWER



CA1 BOARD IMAGE SENSOR

CA1

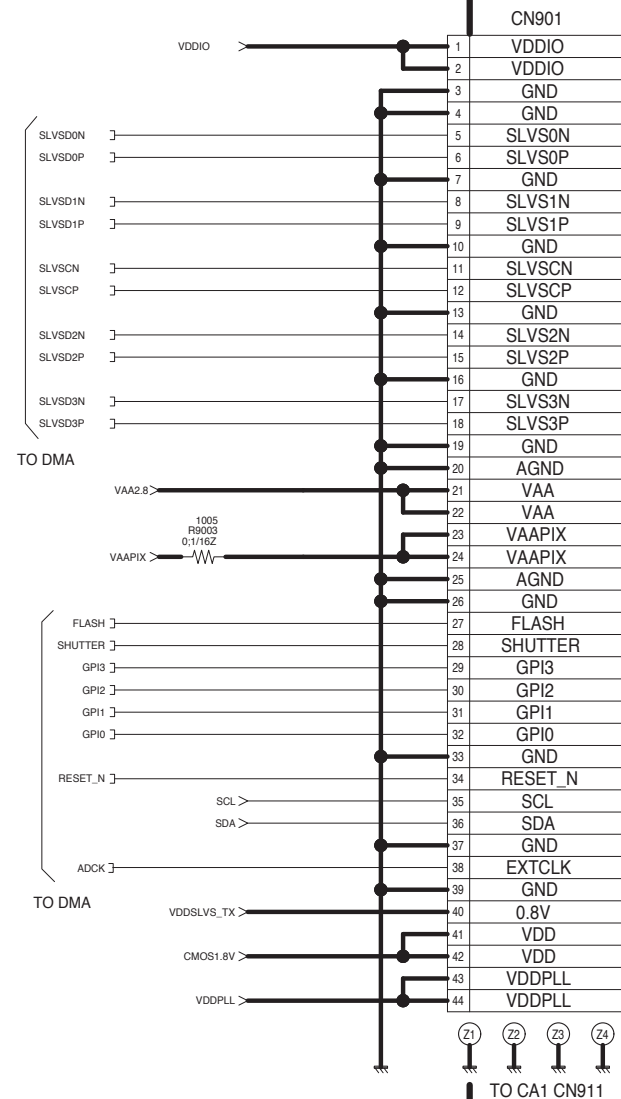
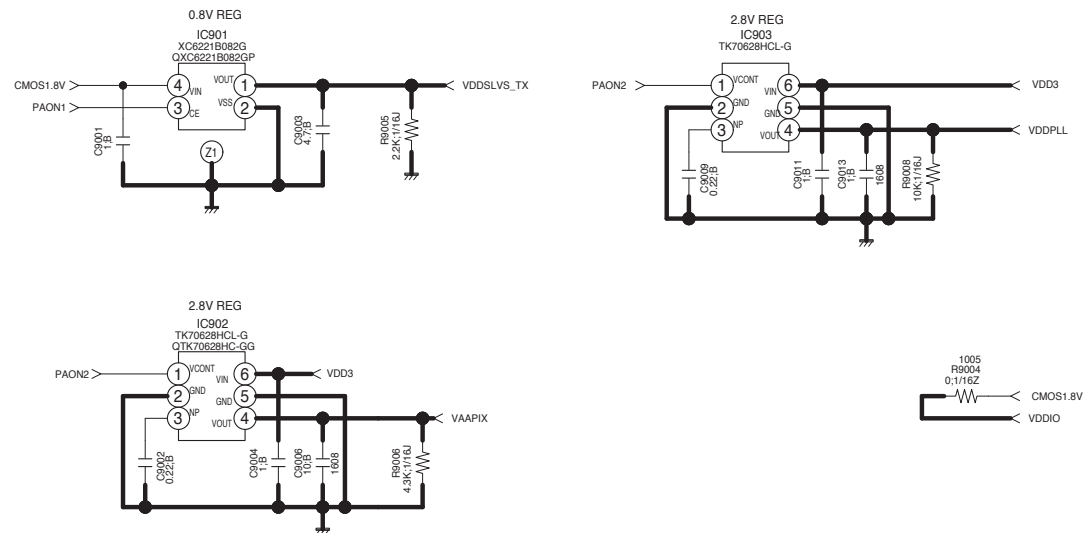
C2-17300/SG314-J
VOLTAGE: VIEW MODE, LCD ON



CP1 BOARD (CAA) LEVEL SHIFT



C1-17300/SG314-J



MAIN CIRCUIT WAVEFORMS

TEST POINT LOCATION	WAVEFORM	TEST POINT LOCATION	WAVEFORM
IC101 PIN AE12 XOUT 1V/div 10ns/div		IC101 PIN AB23 A_D4CKOUT 1V/div 10ns/div	
IC101 PIN P3 ADCK 500mV/div 40ns/div		IC101 PIN AB25 D4CKIN 1V/div 4ns/div	
IC101 PIN AD22 LMCLK 1V/div 20ns/div		IC101 PIN Y2 AMCLK 1V/div 20ns/div	
IC101 PIN W17 LCDVD 1V/div 2ms/div		IC101 PIN W20 CLK24M 1V/div 10ns/div	
IC101 PIN AD20 LCDHD 1V/div 10ps/div		IC101 PIN AD13 VP1XCLK 1V/div 4ns/div	

WF-SG314 MAIN

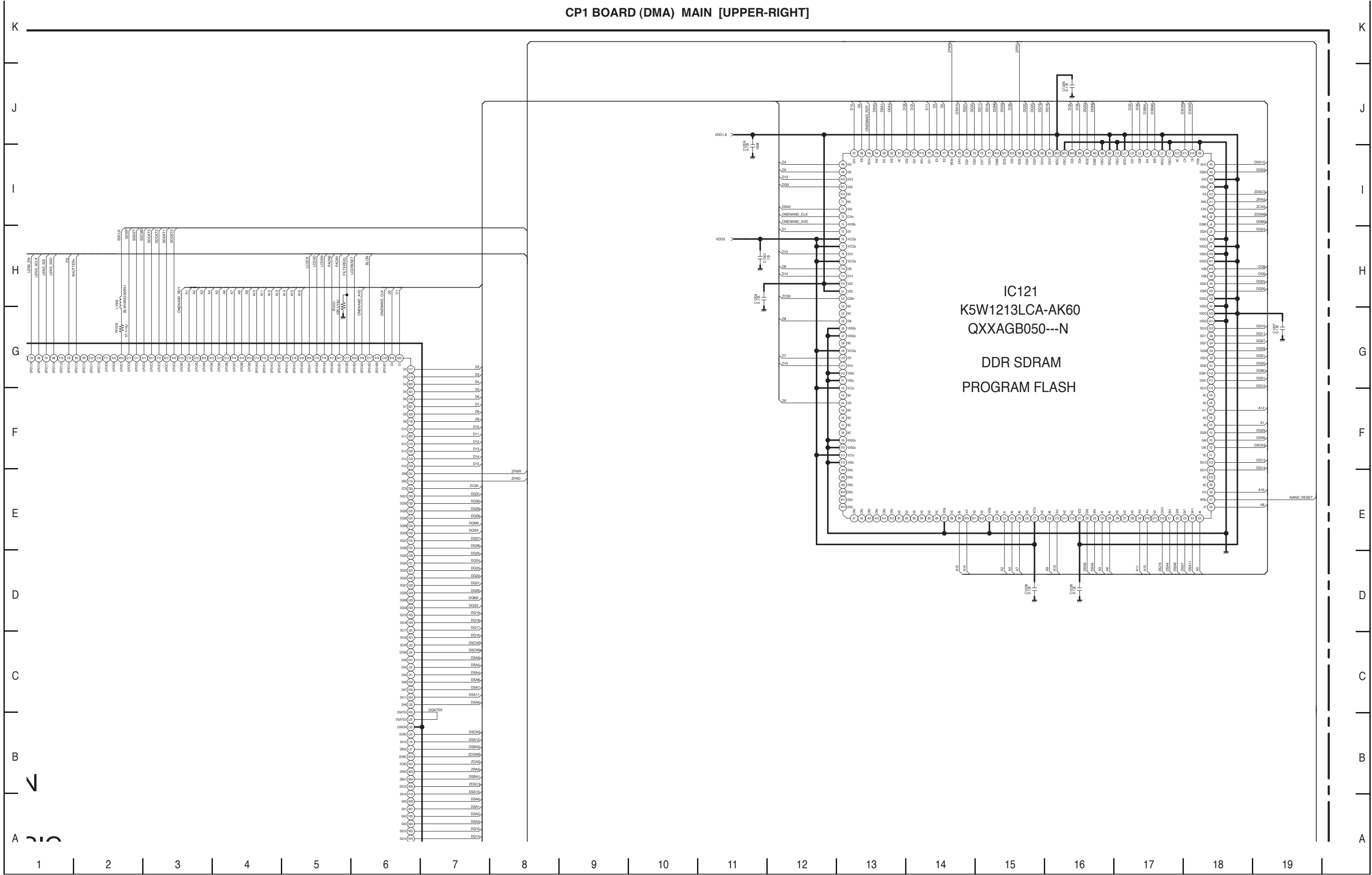
[illegible]

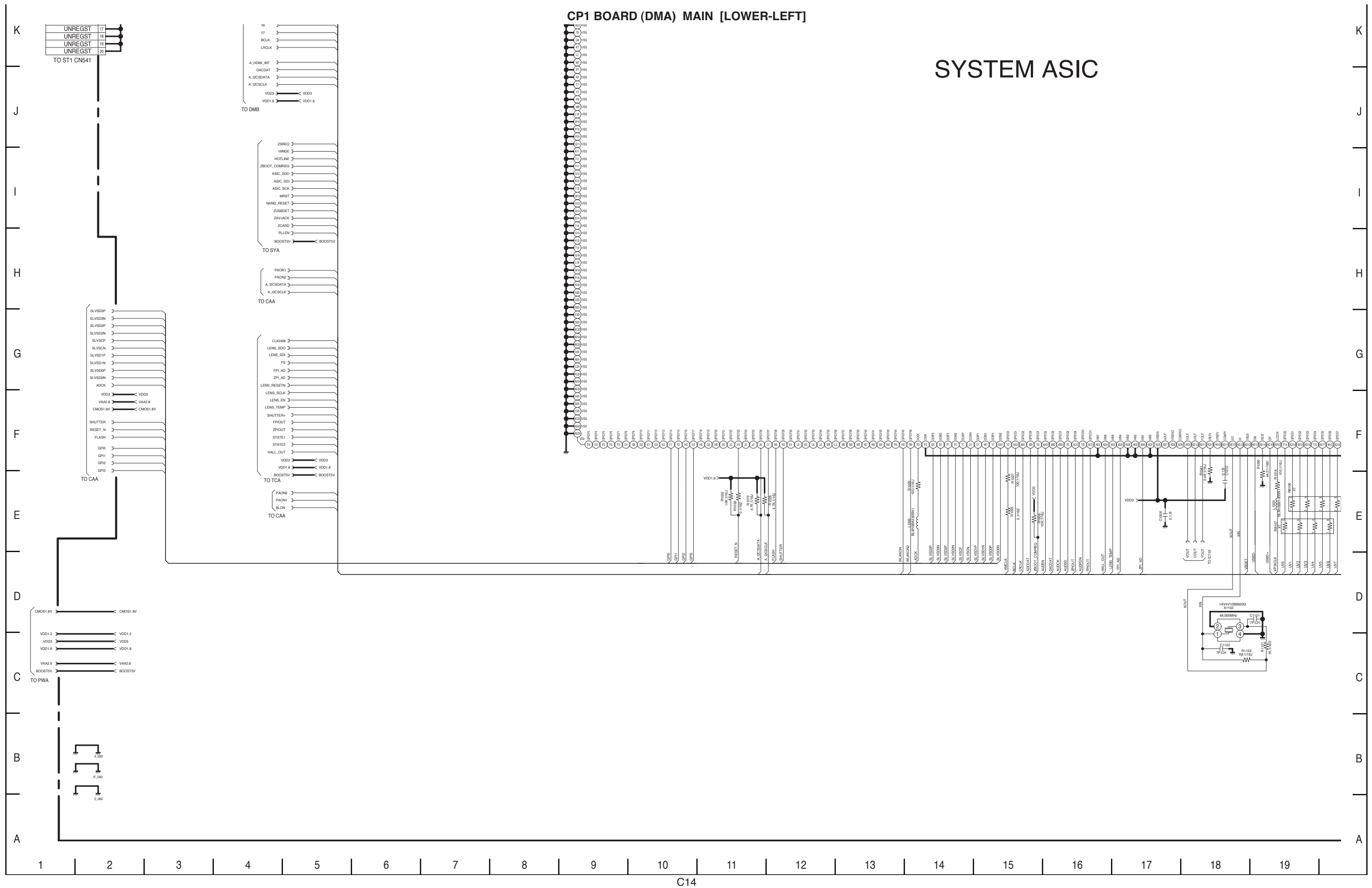
VOLTAGE: VIEW MODE, LCD ON

Система АДИС

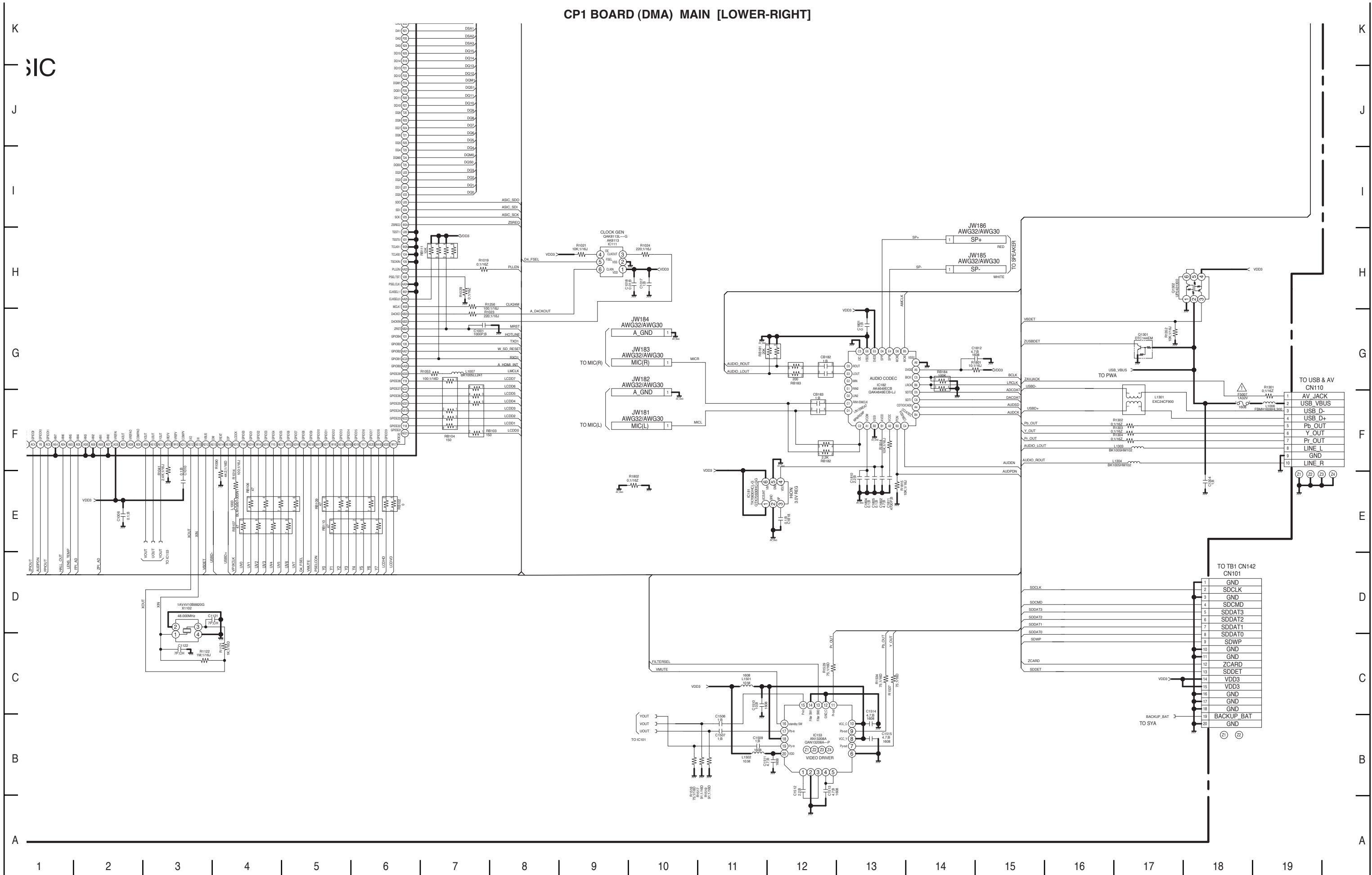
Pin 1 to 20 connection diagram for ST1 CN541. The diagram shows a 20-pin connector with pins 1 through 20. Pins 1 through 20 are connected to various signals. Pin 1 is connected to AL3.2V. Pin 2 is connected to FLCTL. Pin 3 is connected to FLCTL. Pin 4 is connected to ZCHGDONE. Pin 5 is connected to ST_CHG. Pin 6 is connected to ST_CHG. Pin 7 is connected to ZCHGDONE. Pin 8 is connected to BOOSTSV. Pin 9 is connected to BOOSTSV. Pin 10 is connected to GND. Pin 11 is connected to GND. Pin 12 is connected to GND. Pin 13 is connected to GND. Pin 14 is connected to GND. Pin 15 is connected to GND. Pin 16 is connected to UNREGST. Pin 17 is connected to UNREGST. Pin 18 is connected to UNREGST. Pin 19 is connected to UNREGST. Pin 20 is connected to UNREGST. The diagram also shows connections to VPIXCLK, UV0, UV1, UV2, UV3, UV4, UV5, UV6, UV7, Y0, Y1, Y2, Y3, Y4, Y5, Y6, Y7, BCLK, LRLCLK, and A_HDMI_INT.

CP1 BOARD (DMA) MAIN [UPPER-RIGHT]

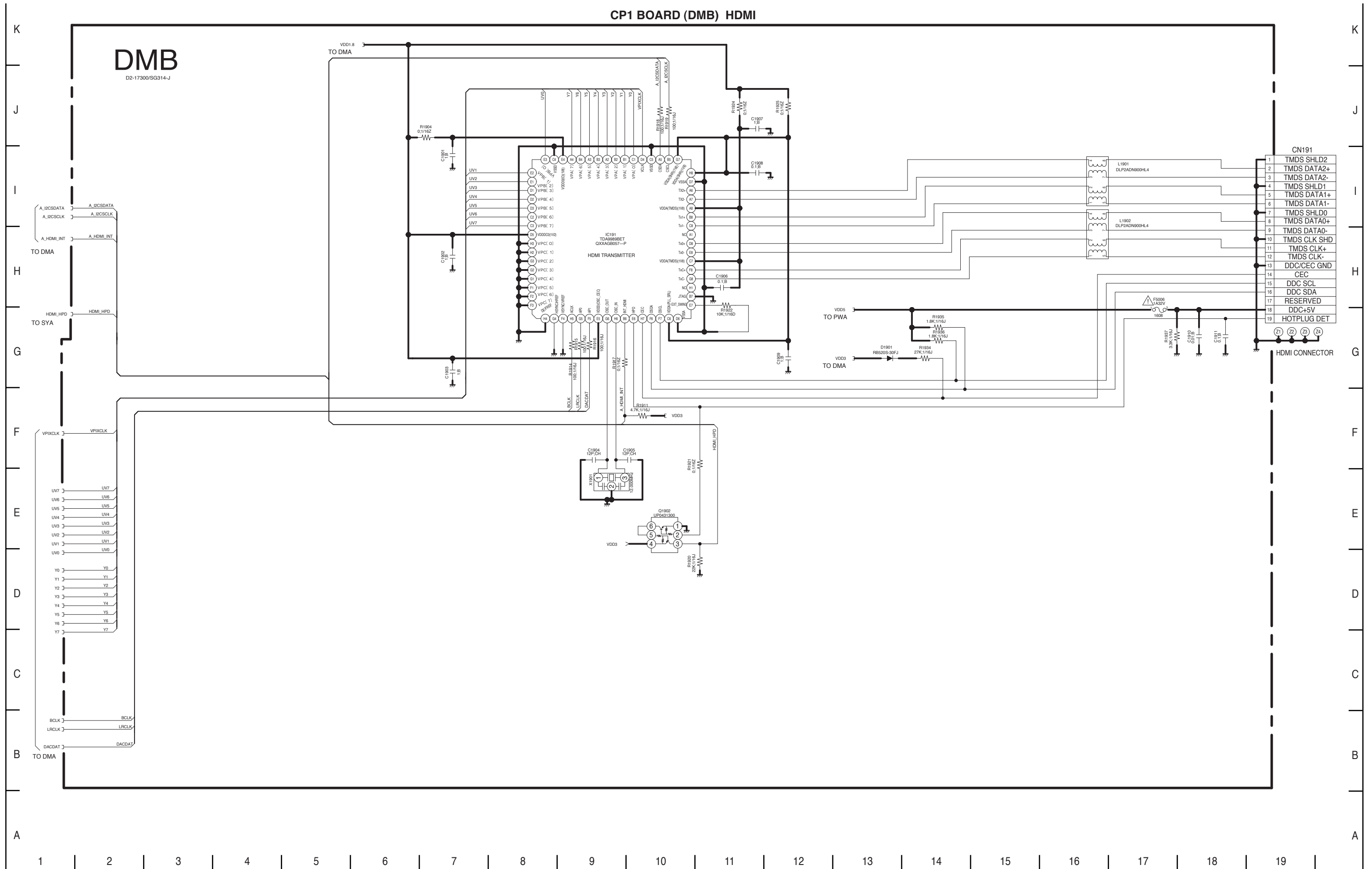




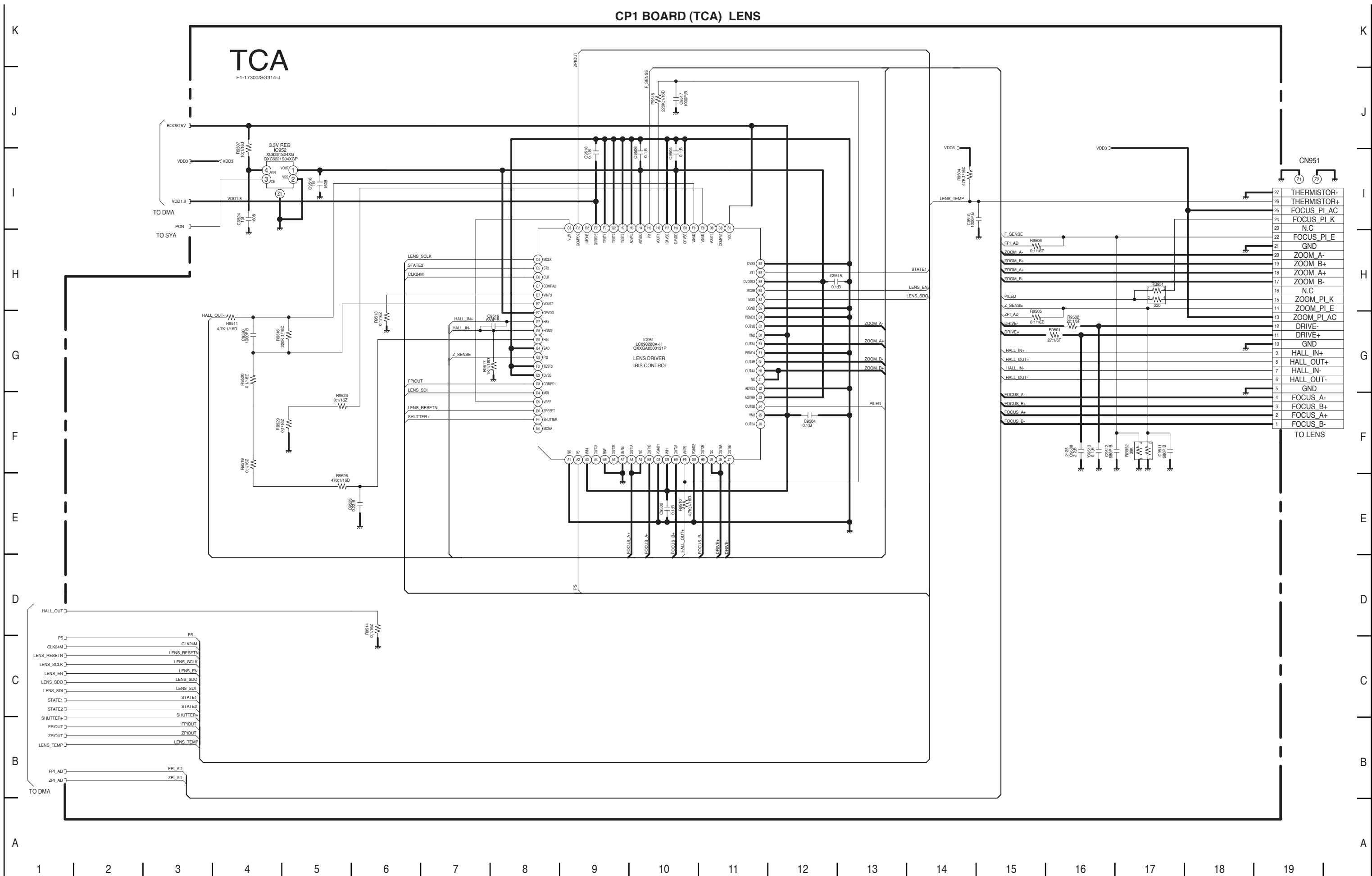
CP1 BOARD (DMA) MAIN [LOWER-RIGHT]



CP1 BOARD (DMB) HDMI



CP1 BOARD (TCA) LENS

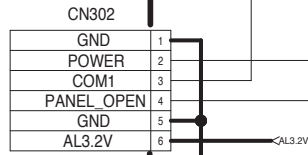
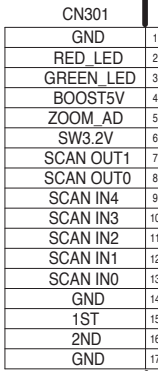


CP1 BOARD (SYA) SYSTEM CONTROL

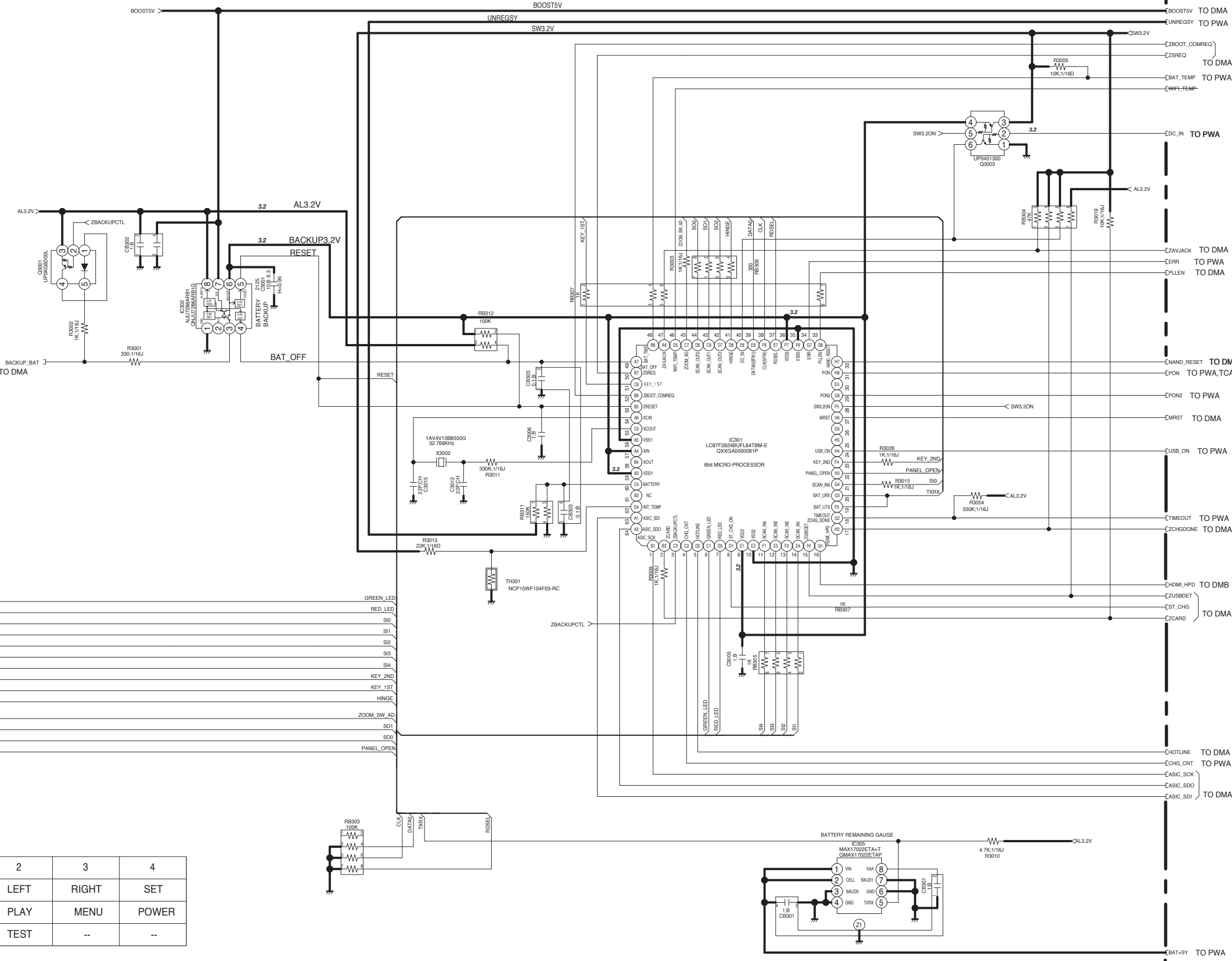
SYA

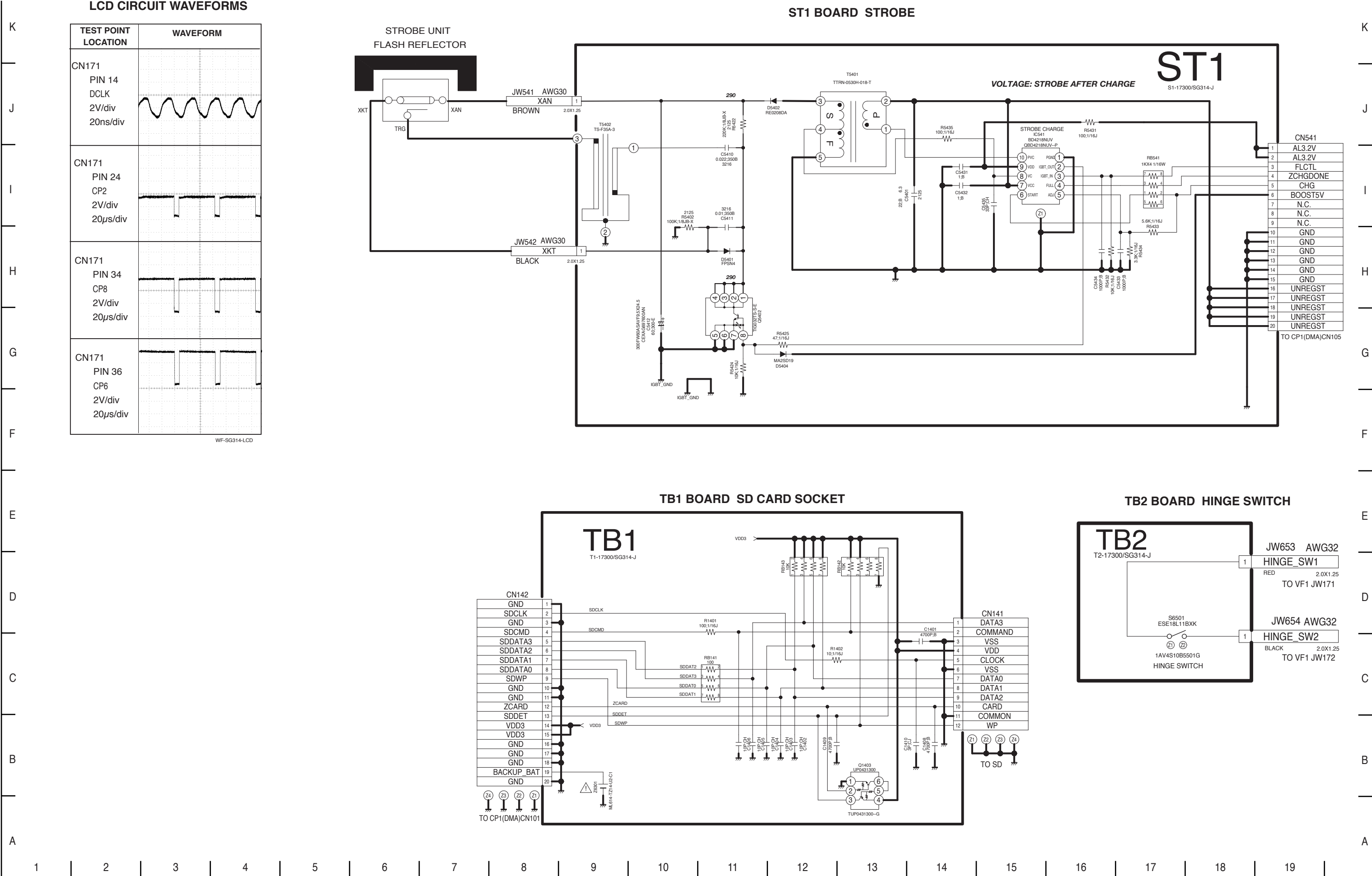
Y1-17300/SG314-J

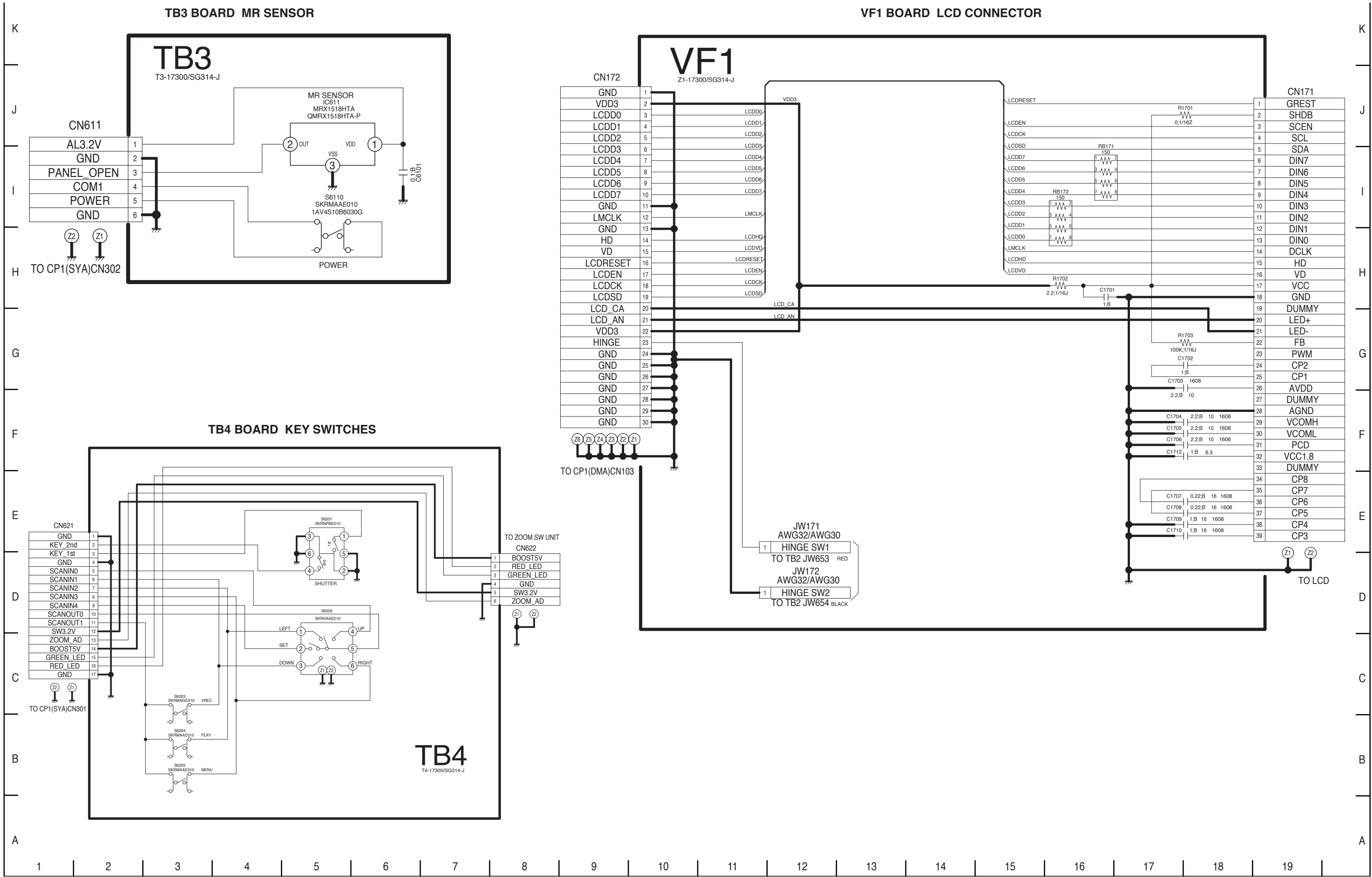
VOLTAGE: VIEW MODE, LCD ON

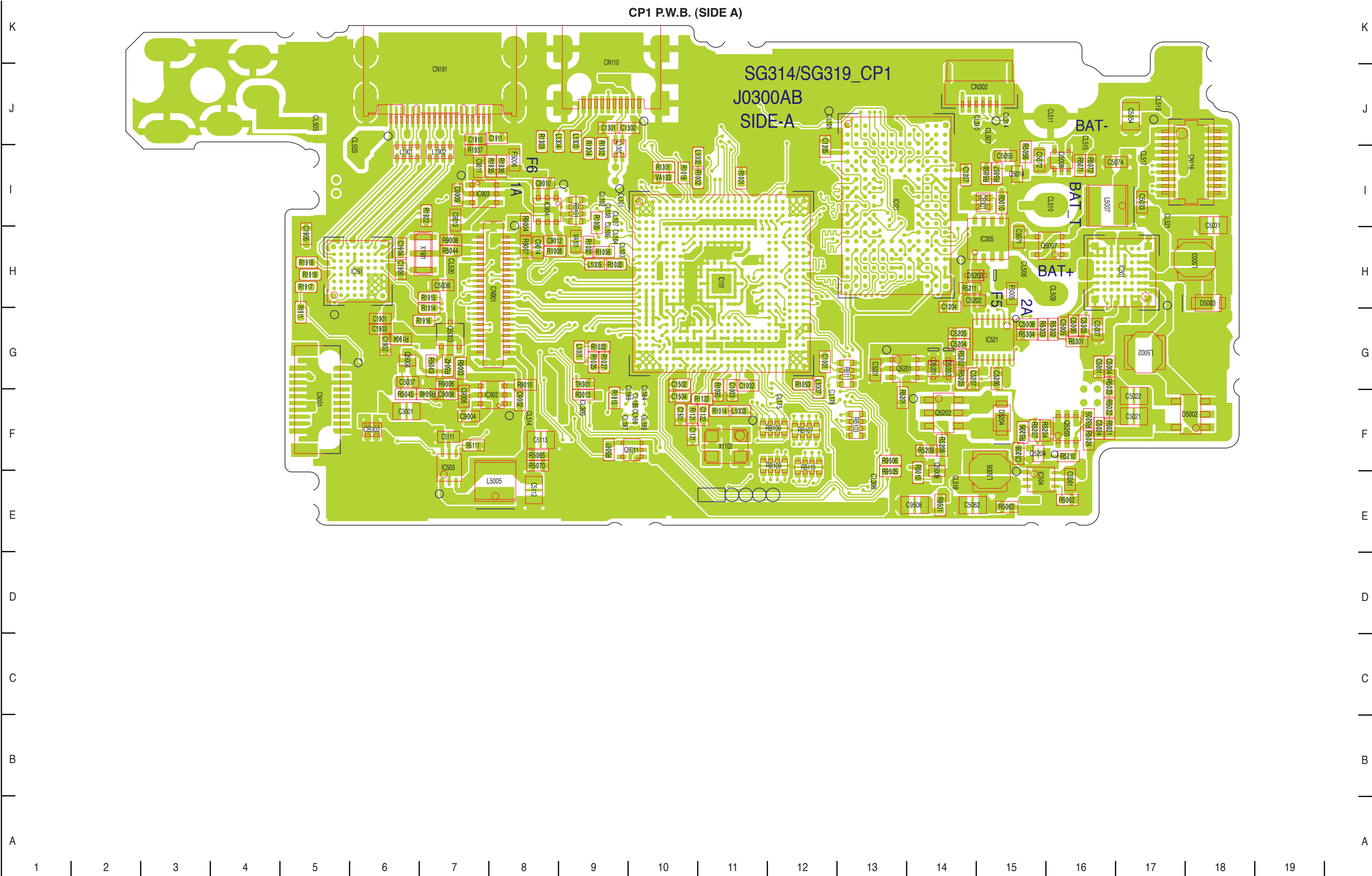


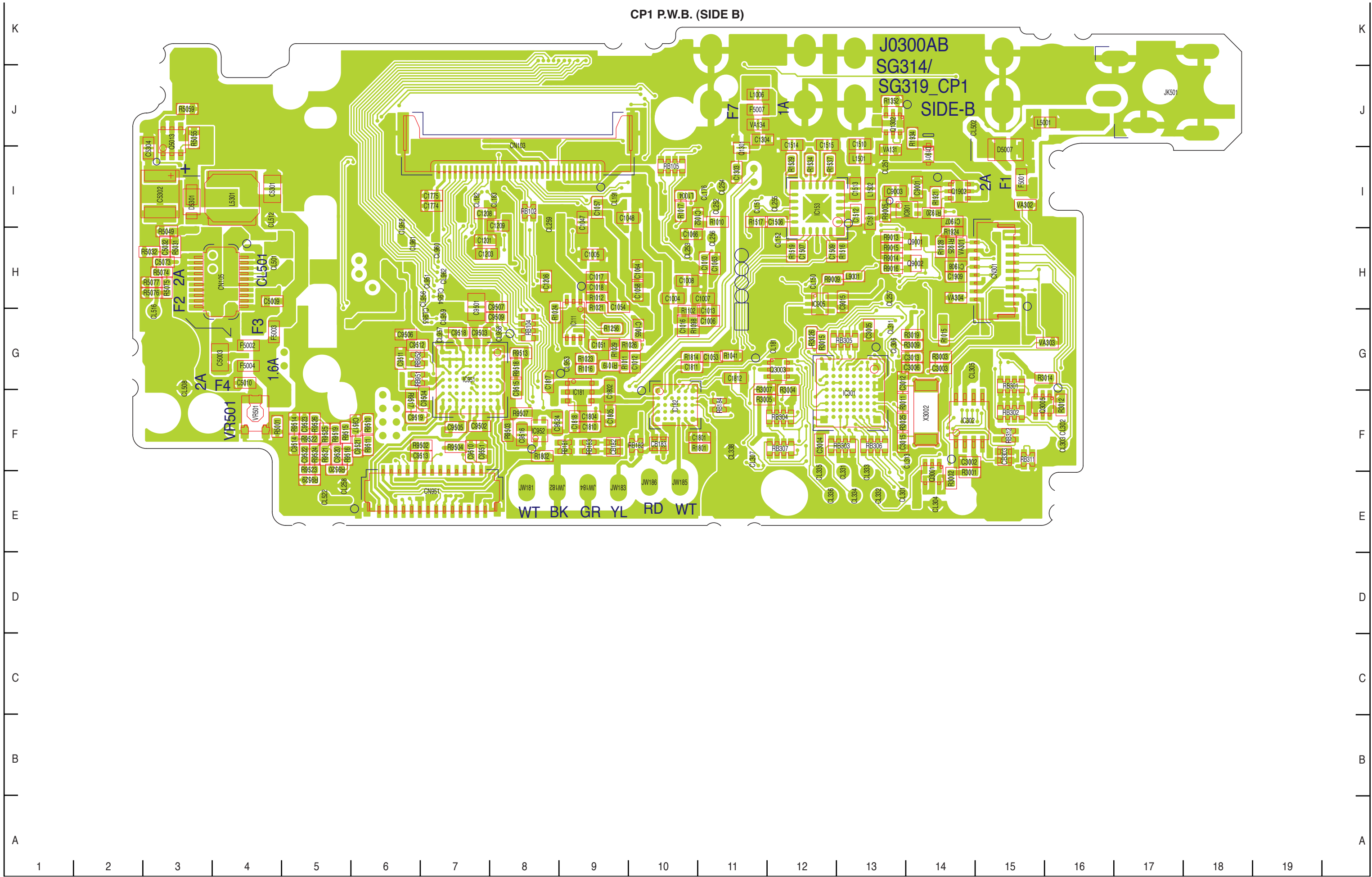
SCAN IN \ SCAN OUT	0	1	2	3	4
0	UP	DOWN	LEFT	RIGHT	SET
1	--	VREC	PLAY	MENU	POWER
2	PW_TEST	--	TEST	--	--

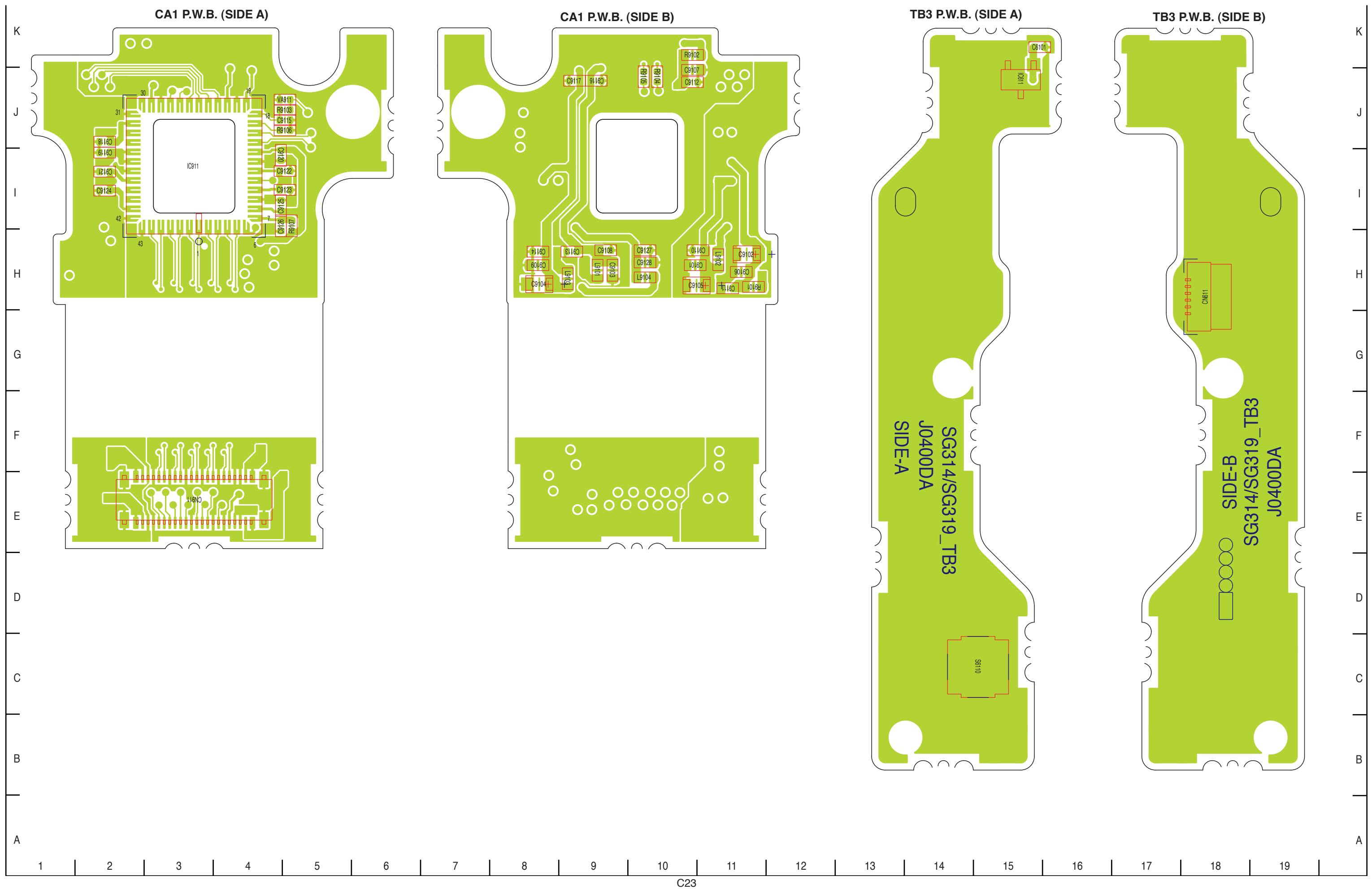


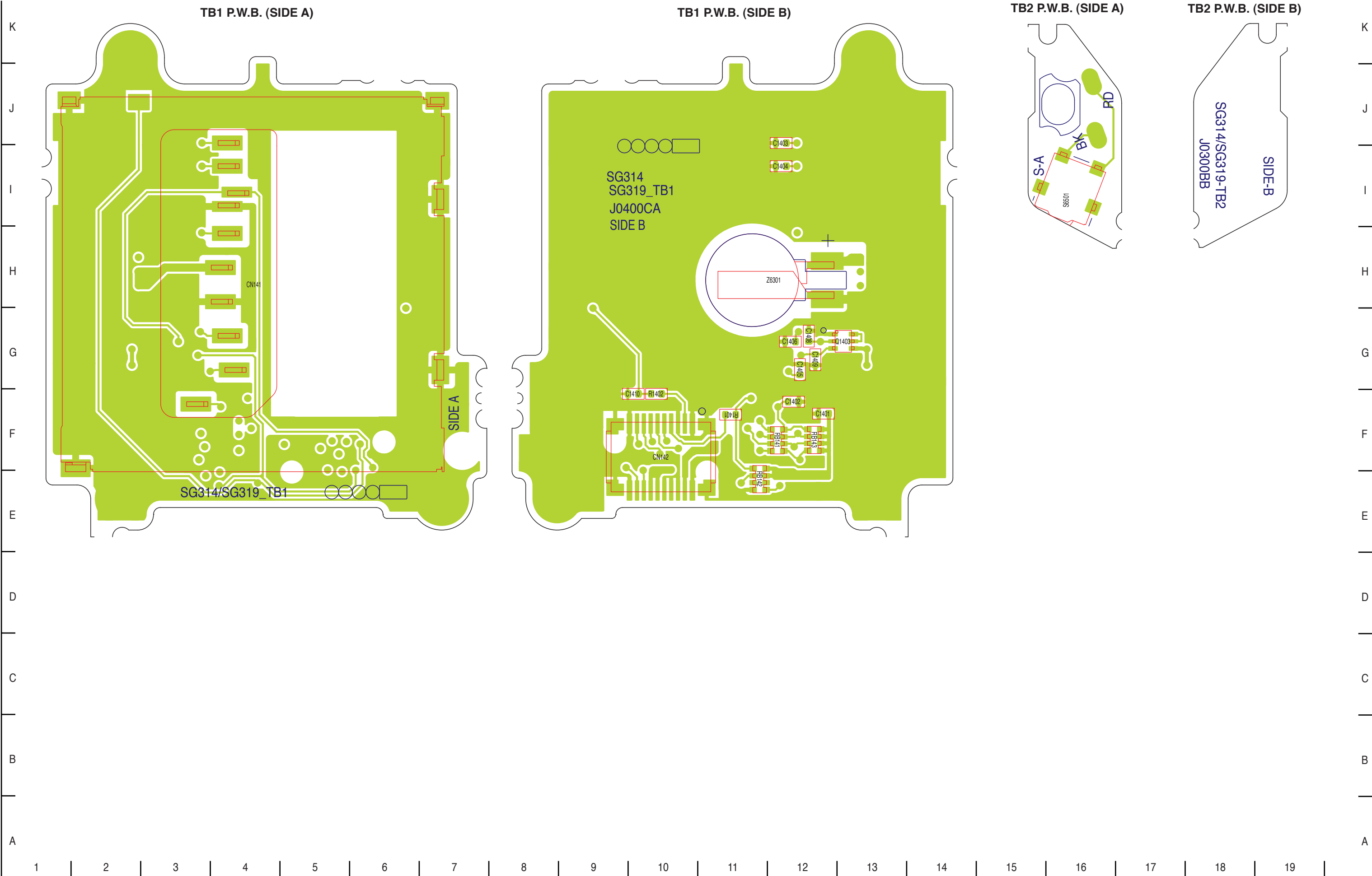


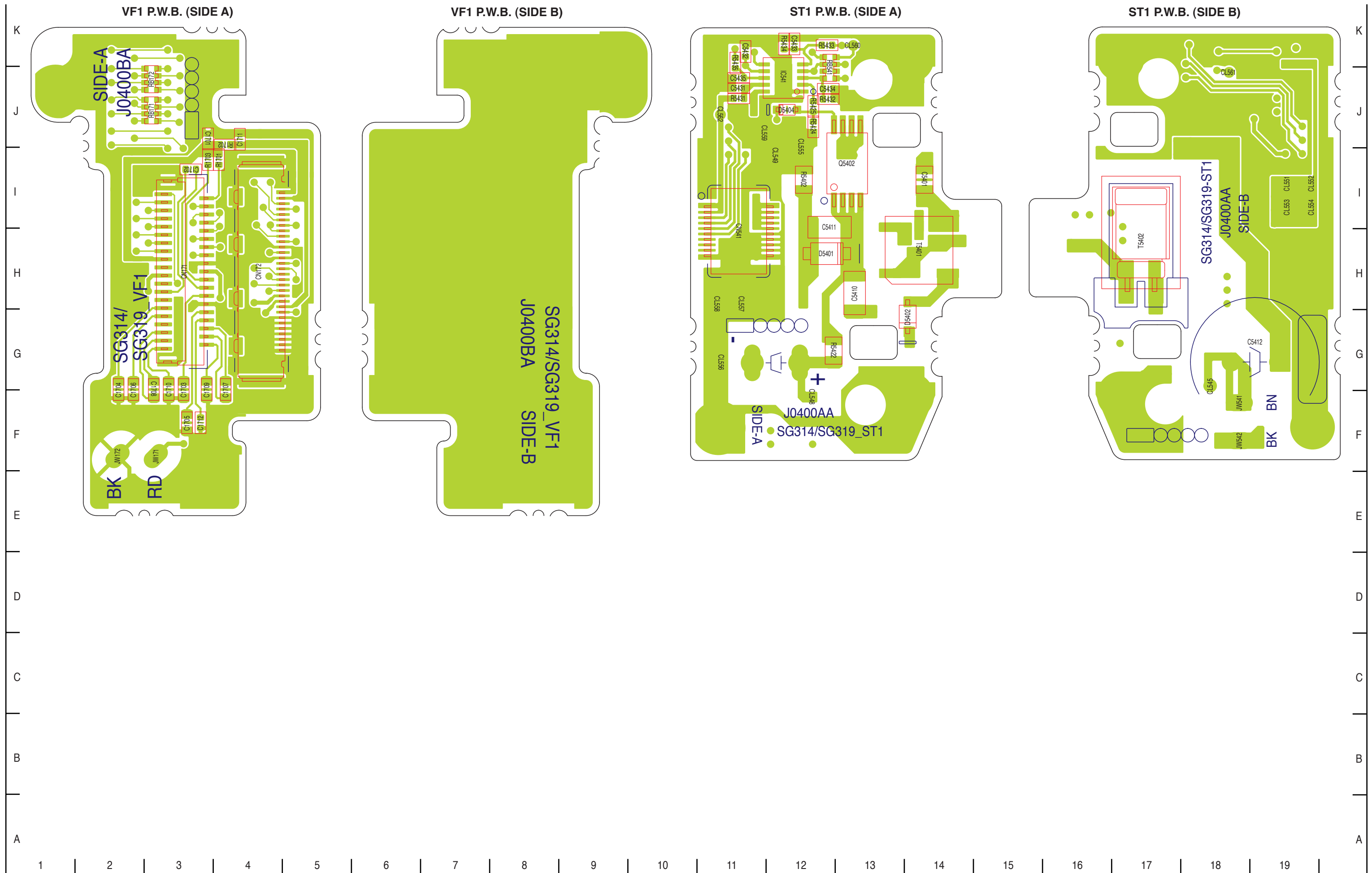


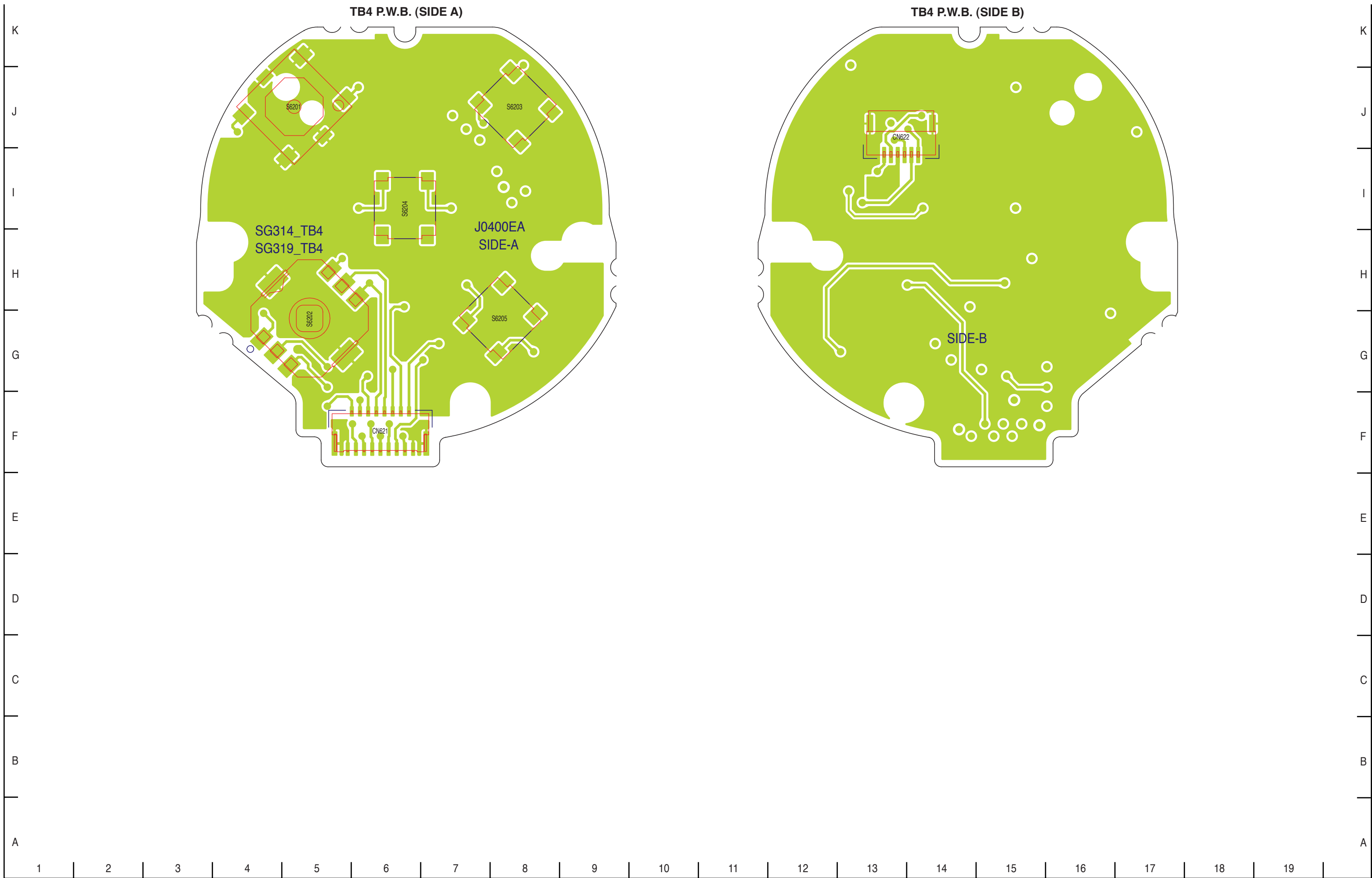


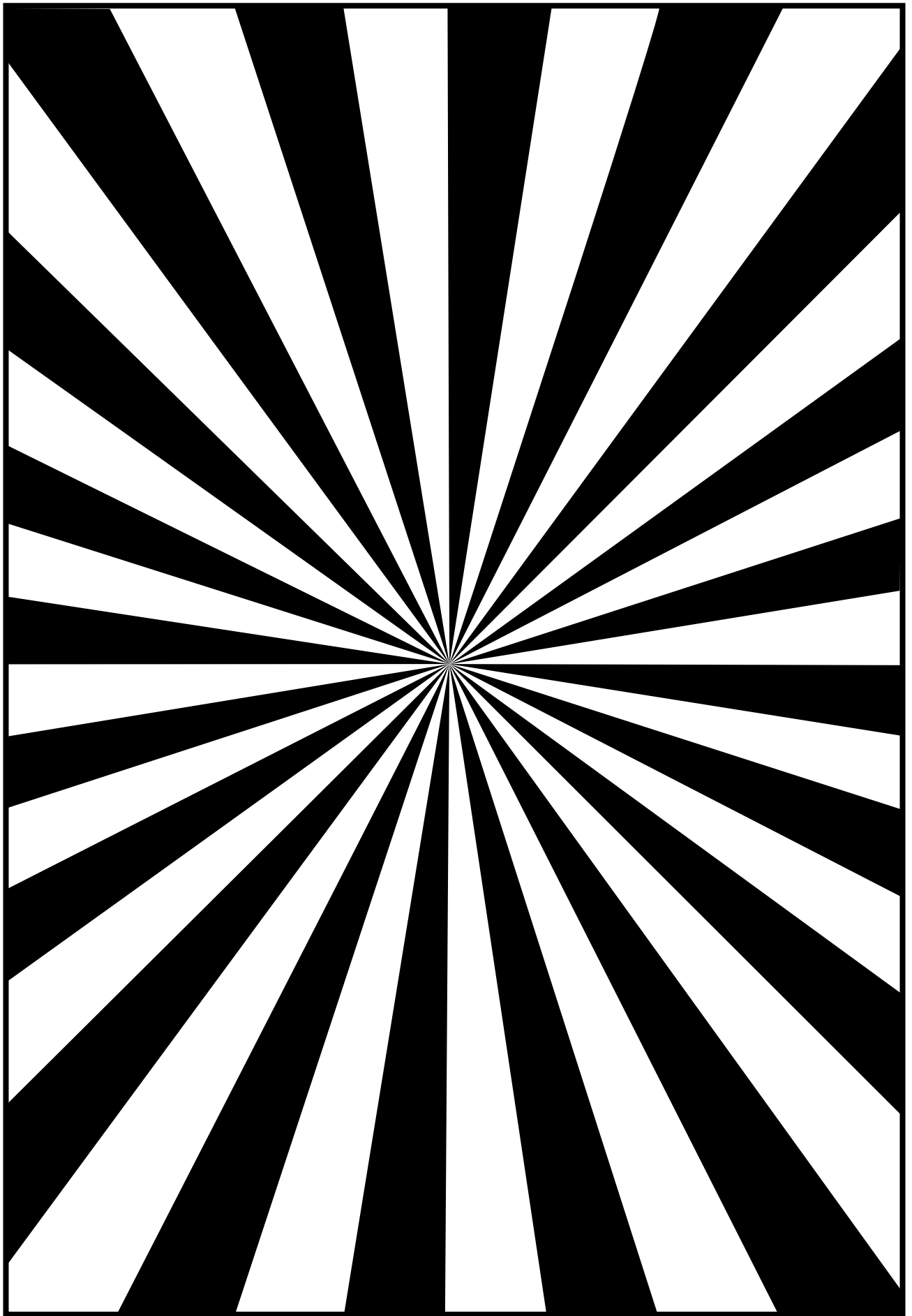














SANYO Electric Co., Ltd.
Osaka, Japan